

# Novel silicon detectors in ALICE at the LHC: the ITS3 and ALICE 3 upgrades

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On behalf of the ALICE collaboration

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6th September 2023, Quark Matter

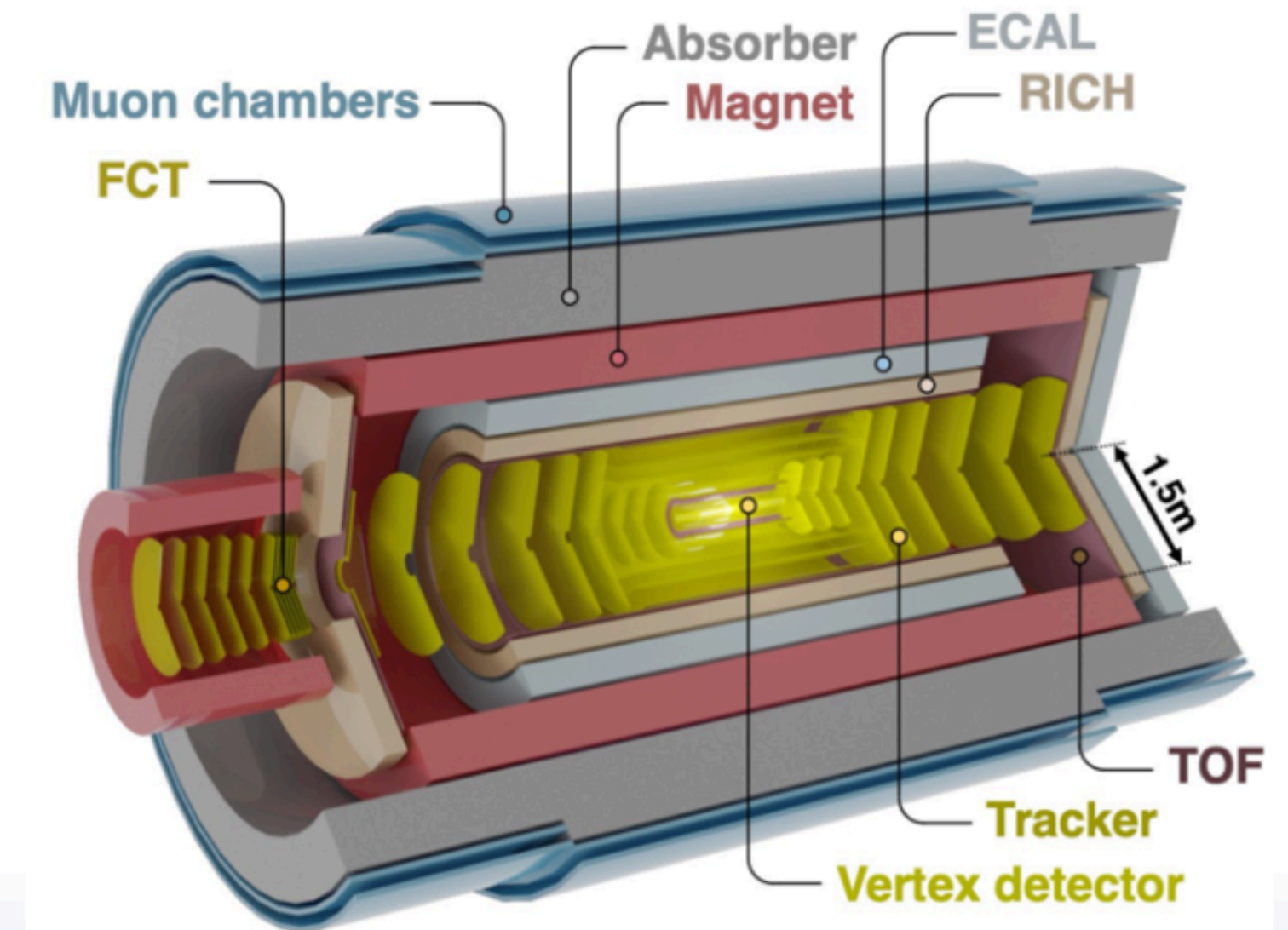
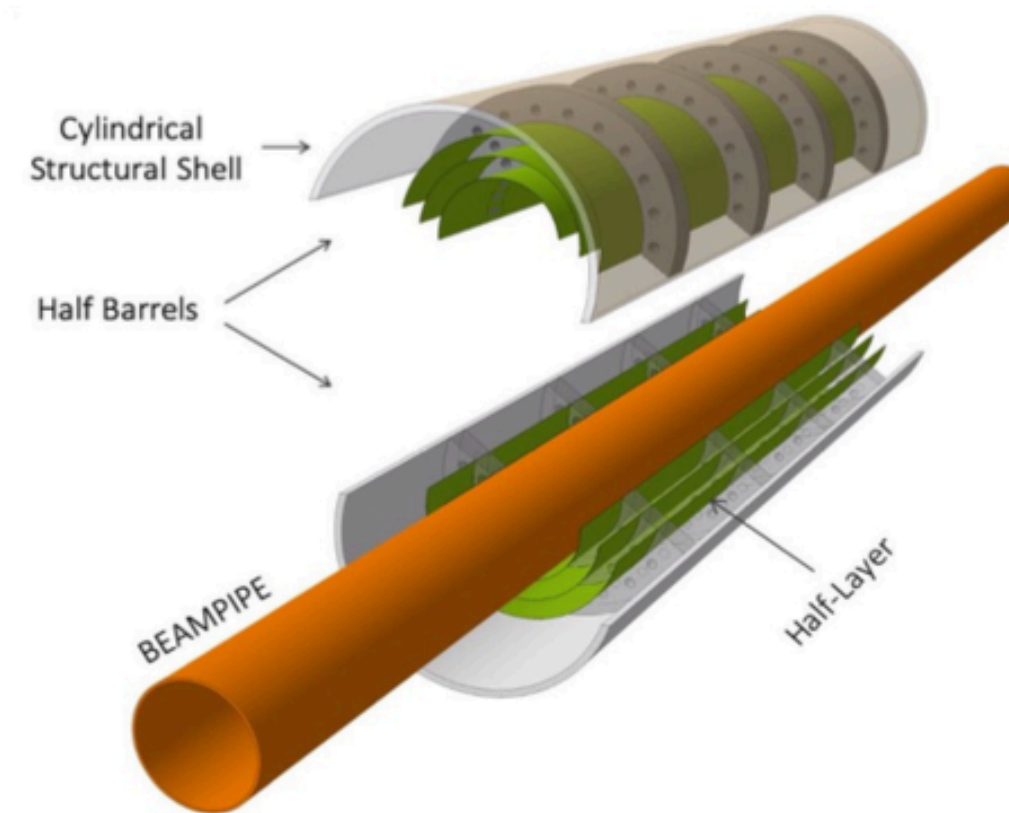
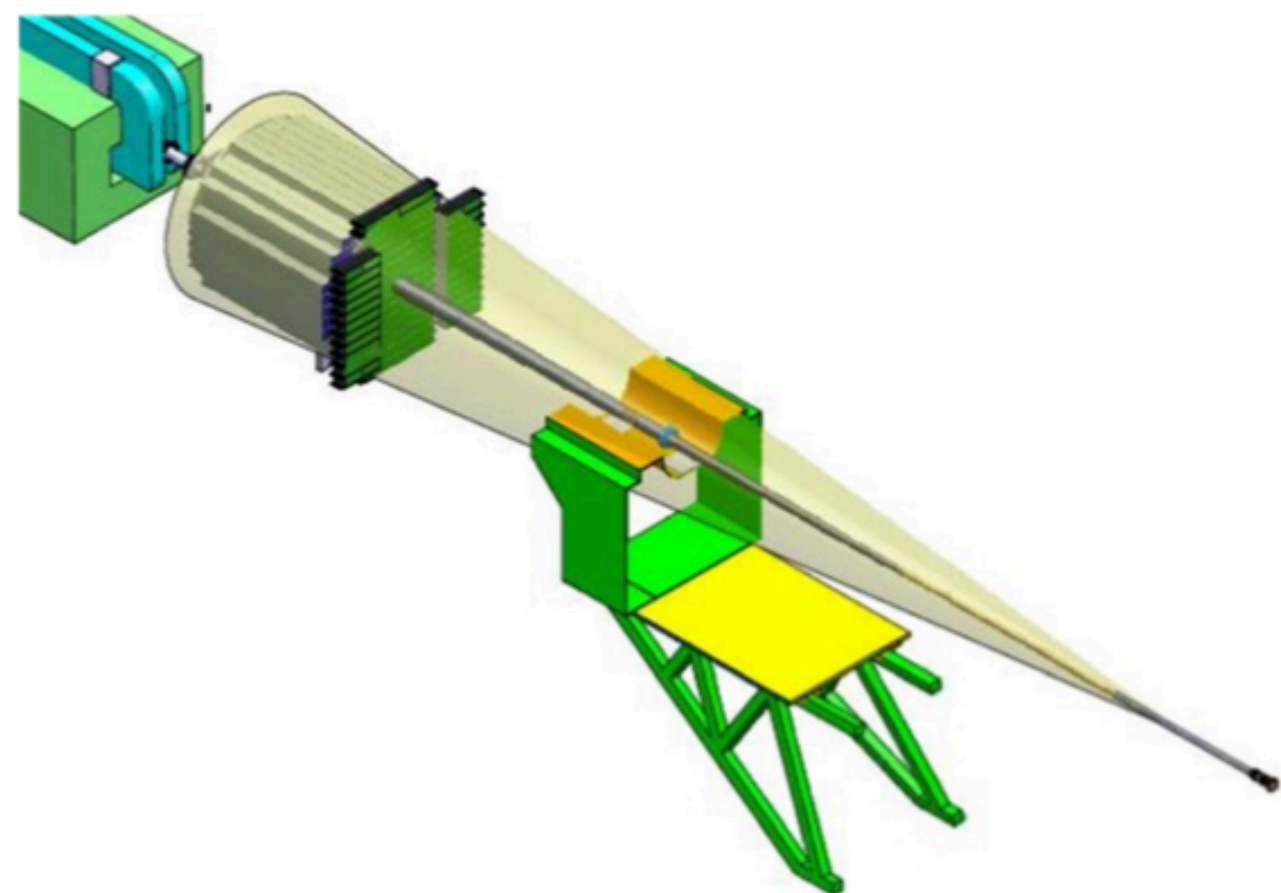


# ALICE Upgrades timeline



**LS3: FoCal & ITS3**

**LS4: ALICE 3**



**FoCal: next talk by Florian Jonas**

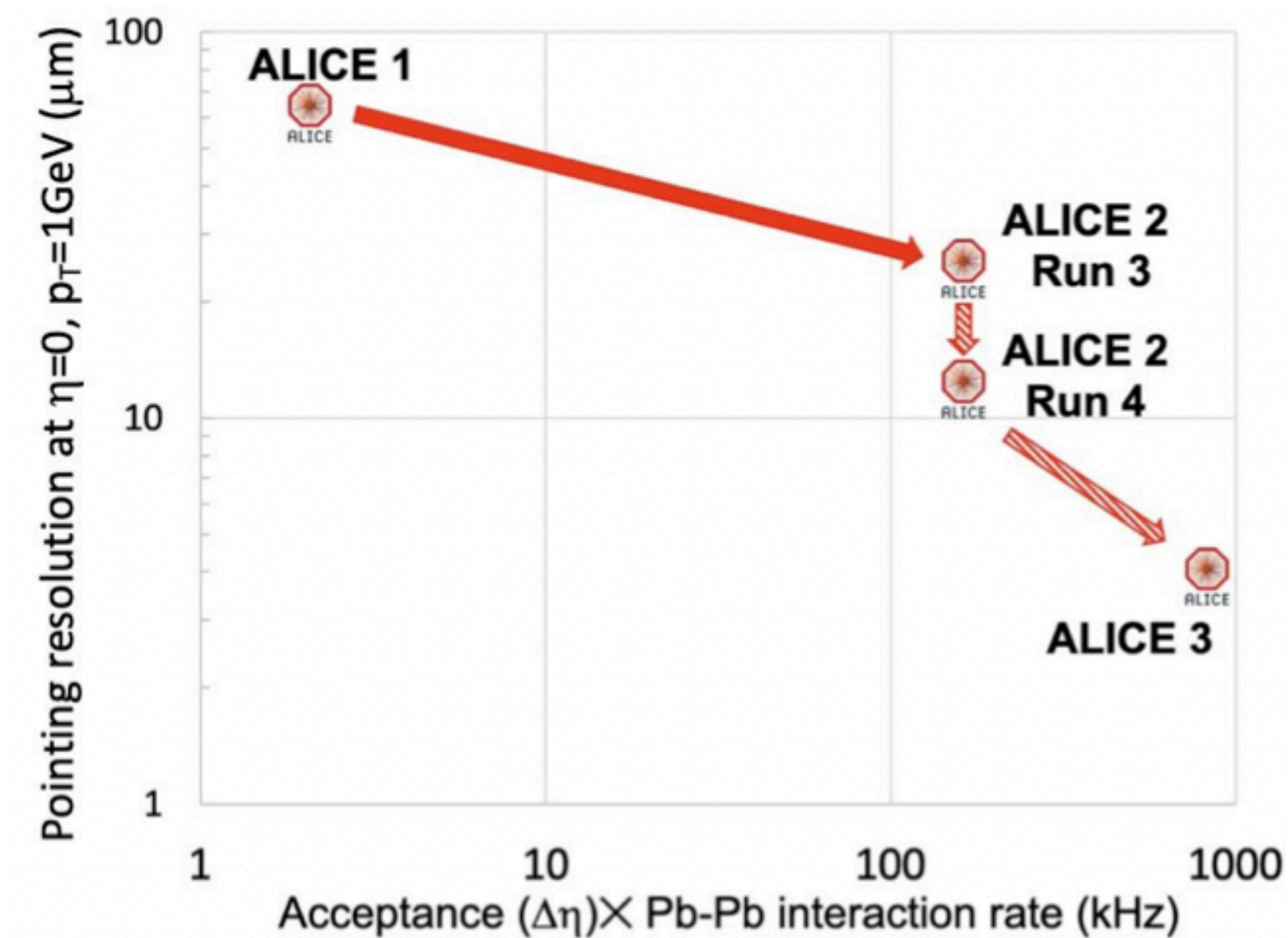
# Upgrade motivations and requirements

## Main physics motivations:

- **Heavy flavours** hadrons at low  $p_T$  (charm and beauty interaction and hadronisation in the QGP)
- **Quarkonia** down to  $p_T = 0$  (melting and regeneration in the QGP)
- **Thermal dileptons**, photons, vector mesons (thermal radiation, chiral symmetry restoration)
- Precision measurements of **light (hyper)nuclei** and searches for charmed hypernuclei

## Main requirements:

- Increased effective acceptance (acceptance x readout rate)
- Improved tracking and vertexing performance at low  $p_T$  for background suppression
- Preserve in ALICE 2 and enhance in ALICE 3 particle identification (PID) capabilities

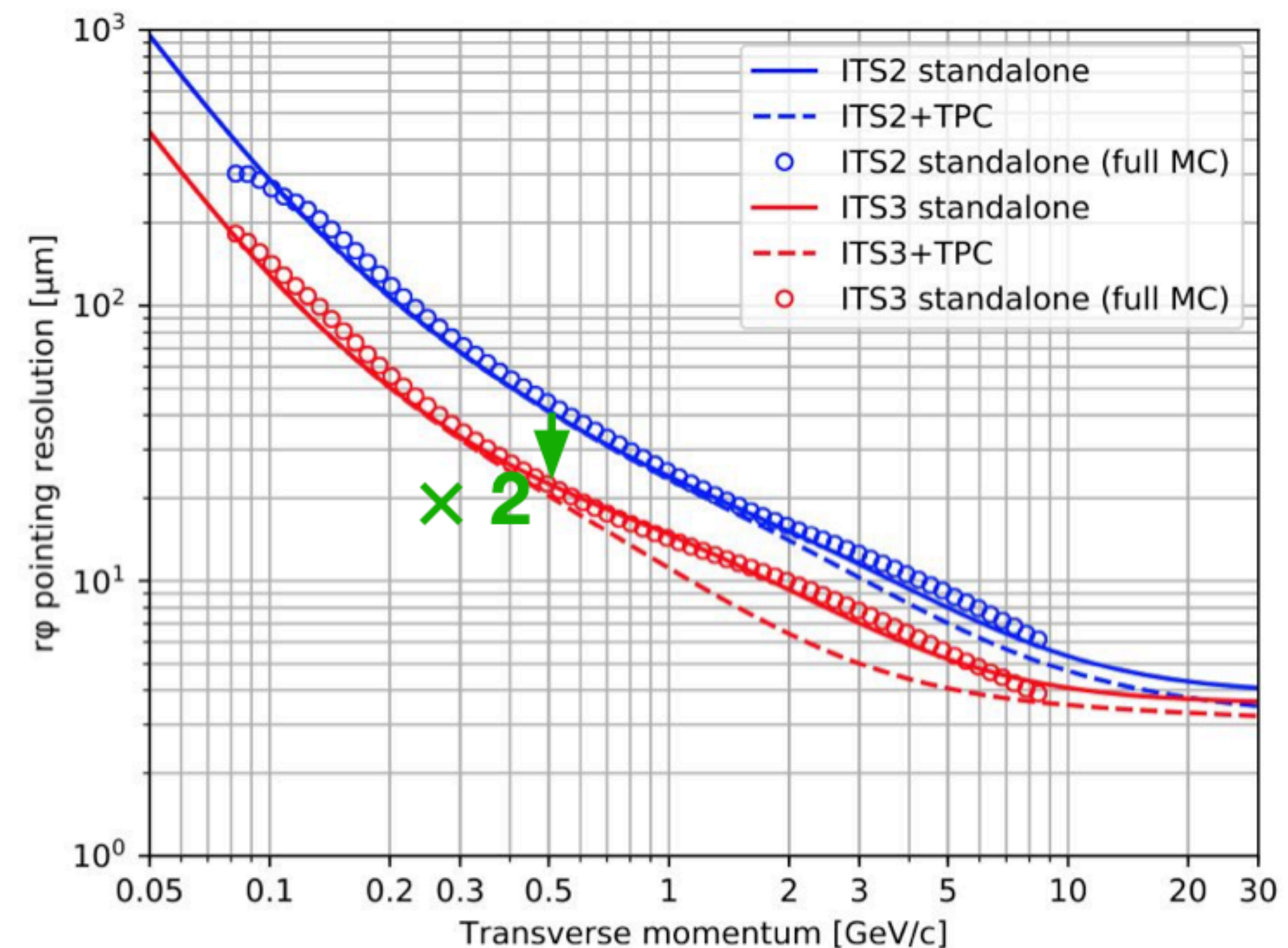
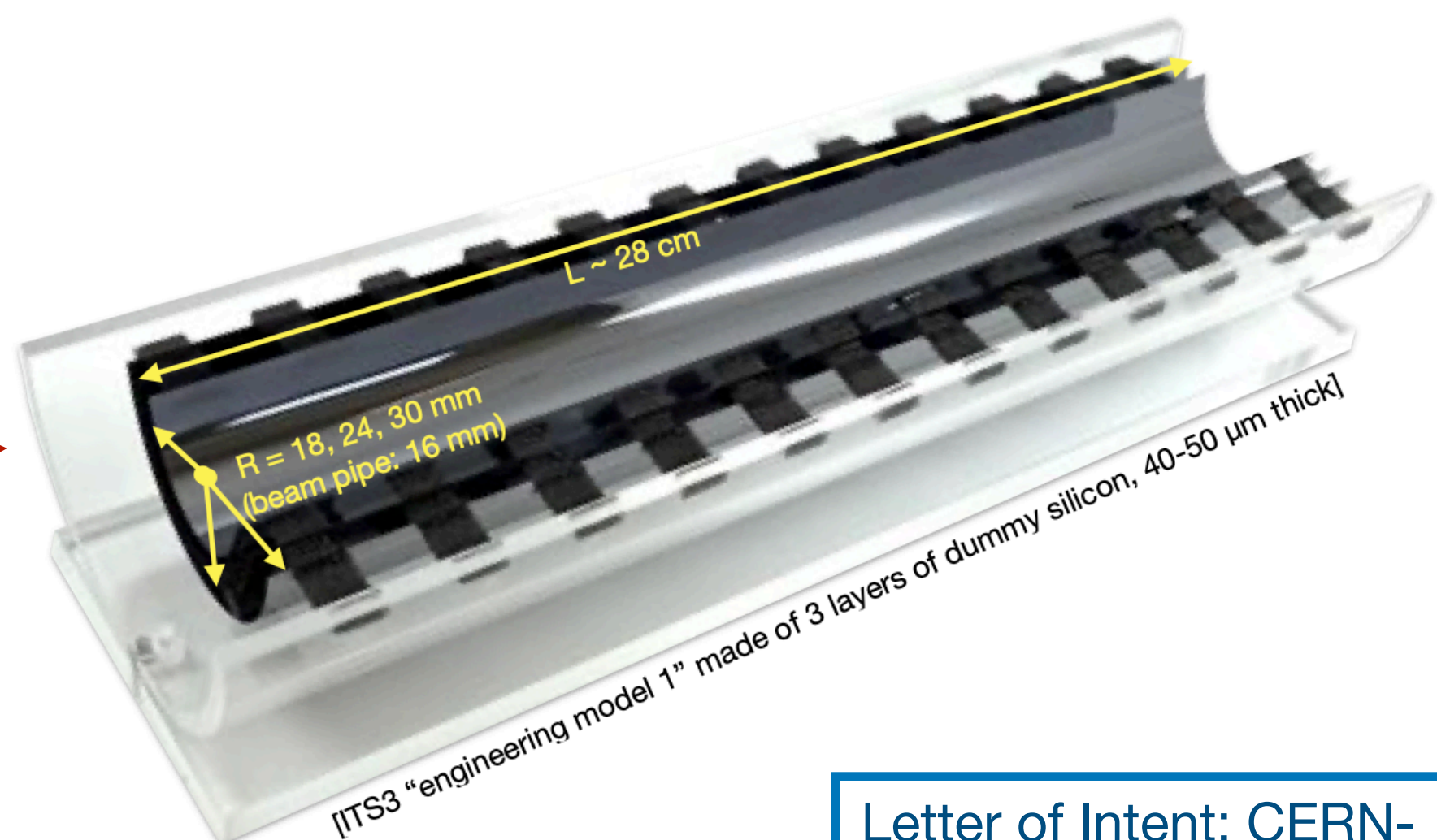
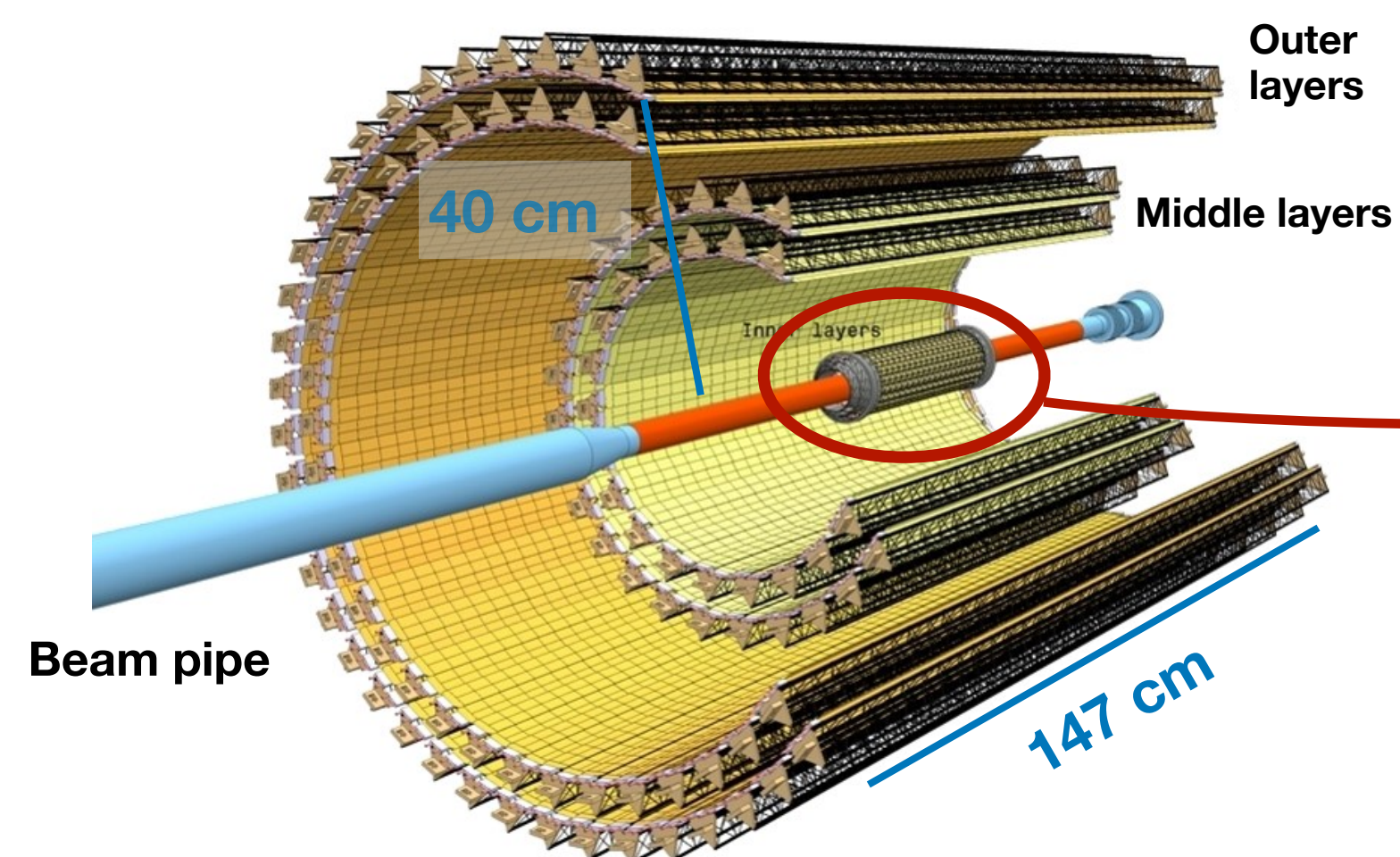




# ALICE ITS3

Replacing the 3 innermost layers with new ultra-light, truly cylindrical layers:

- Reduced material budget (from 0.35% to 0.05%  $X_0$ )
- Closer to the interaction point (from 23 to 18 mm)
- Improved vertexing performance and reduced backgrounds for heavy-flavour signals and for low-mass dielectrons



Letter of Intent: CERN-LHCC-2019-018



# ALICE ITS3

ITS3 engineering model made of dummy silicon

18 mm

24 mm

30 mm



## Bending

The idea is to make use of the flexible nature of thin silicon:

- Thinned down sensors to 50  $\mu\text{m}$ , making them flexible
- Bent to the target radii and mechanically held in place by carbon foam spacers

## Stitching

Another key ingredient is the stitching:

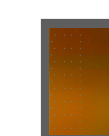
- ITS2 sensors are 30x15 mm (limited by reticle size), our target is 280x94 mm
- For such a large area stitching is mandatory: a true single piece of silicon

## Technology validation

R&D started on new sensors to face the new challenges:

- 65nm CMOS imaging technology tested for validation

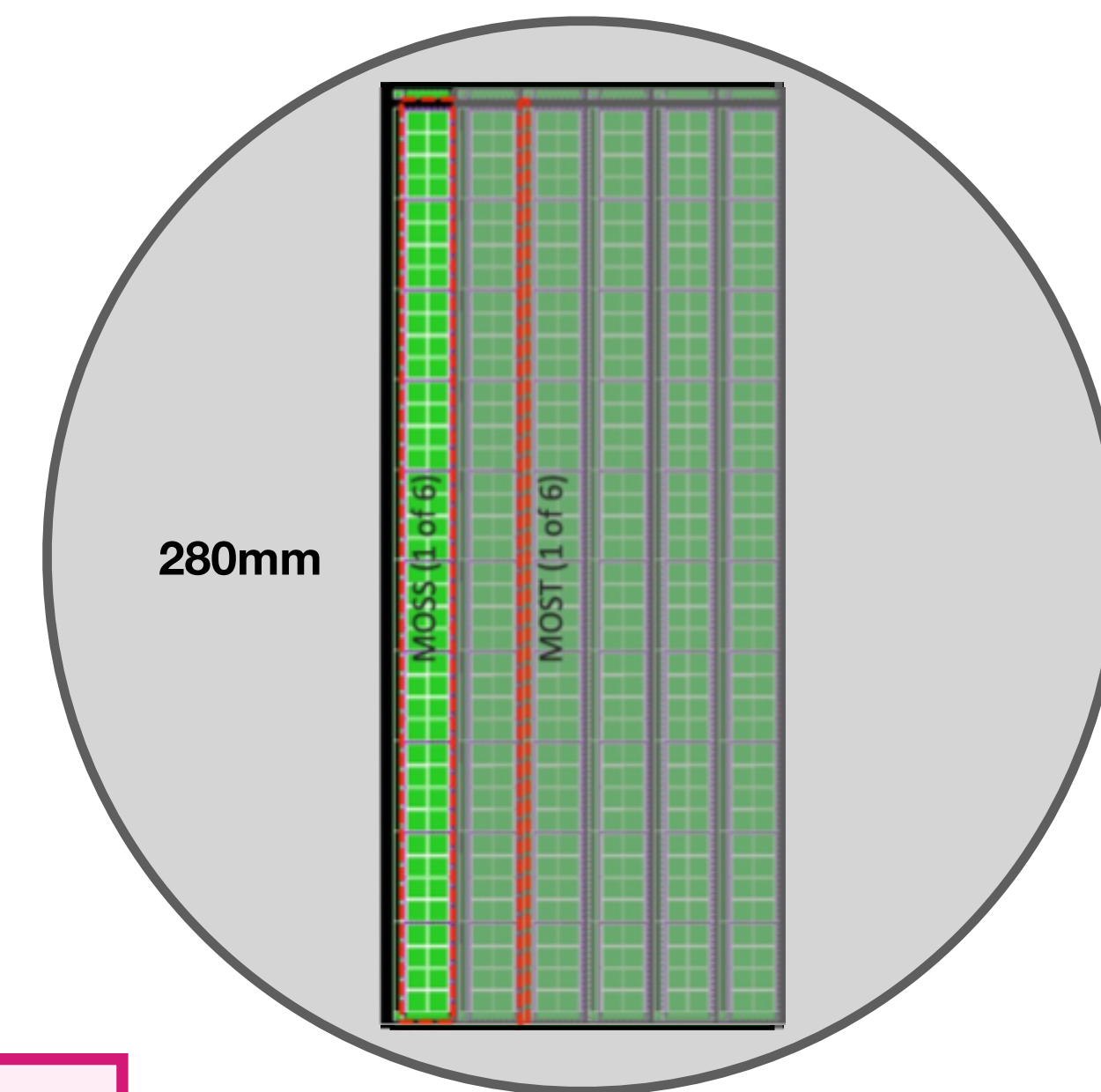
30mm



15mm



280mm



94mm

**All three innovative developments pioneered by ALICE and never used before in HEP!**



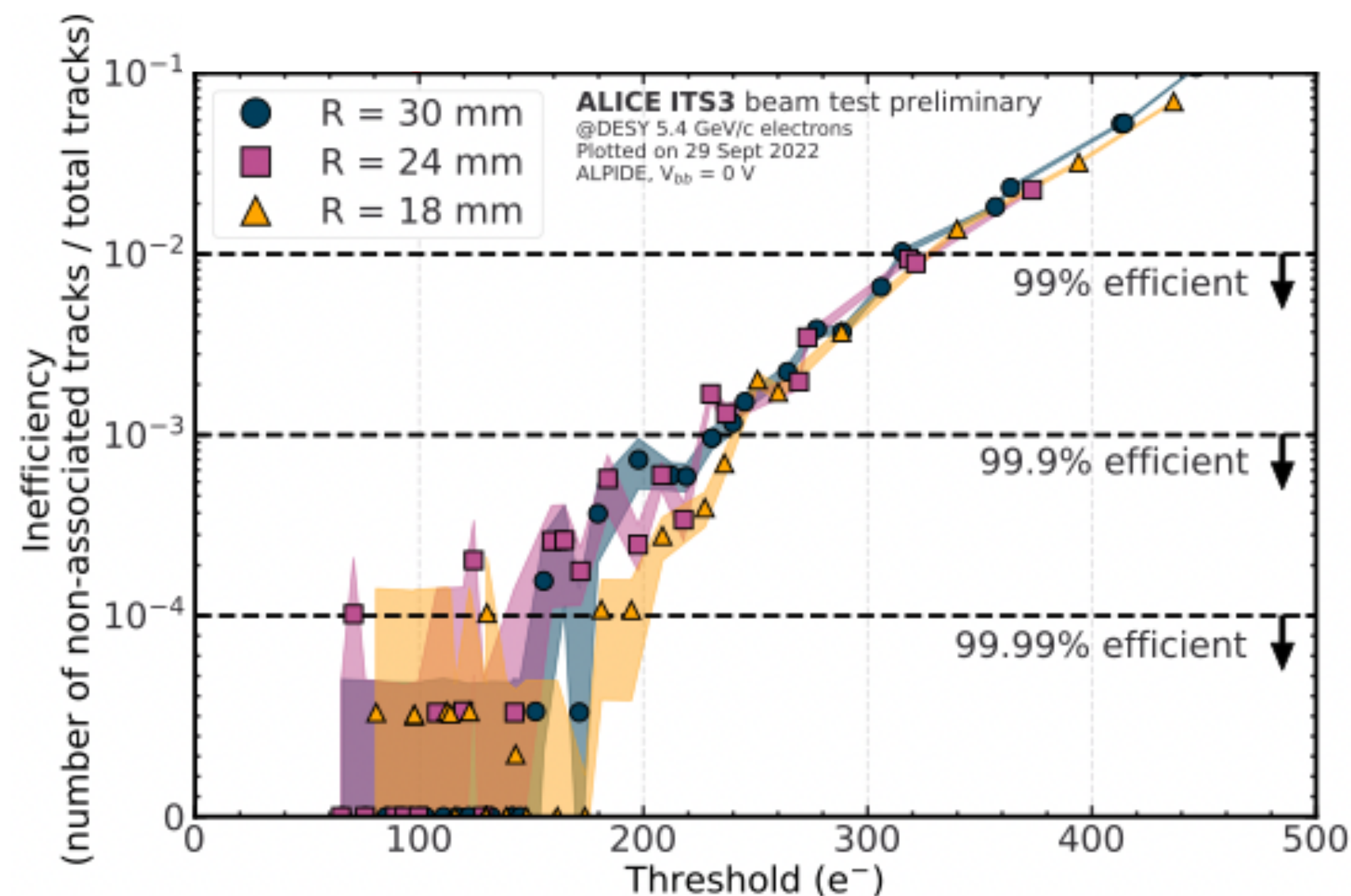
# Sensor bending

Bending procedure tested in different ways and at different radii on ITS2 ALPIDEs:

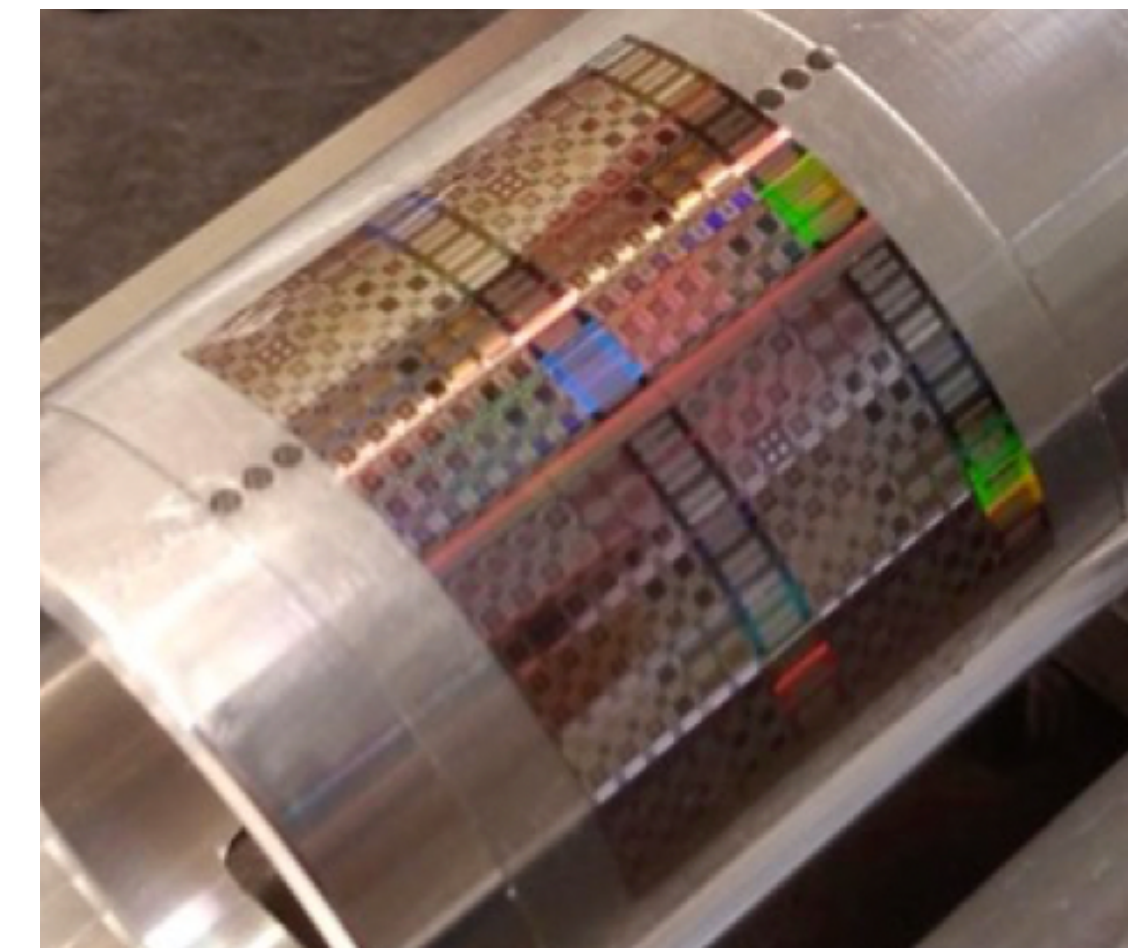
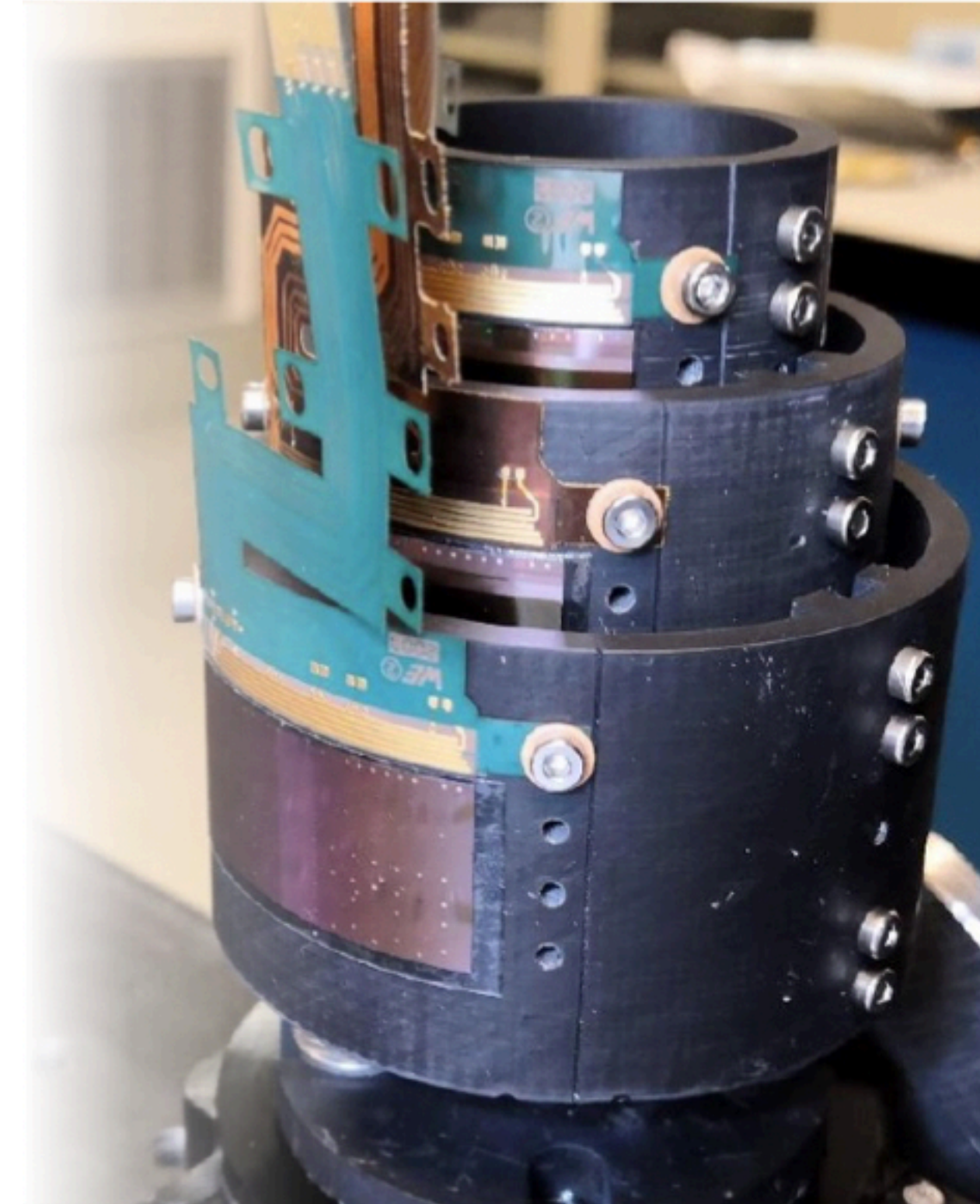
- No degradation, work as flat chips! [2021-166280](#)

Down-scaled mock-up of the final ITS3 was produced with six bent ALPIDEs ( $\mu$ ITS3):

- Results from beam tests show no differences in performance among different bending radii



Also 65 nm technology prototypes are being tested, new results soon!

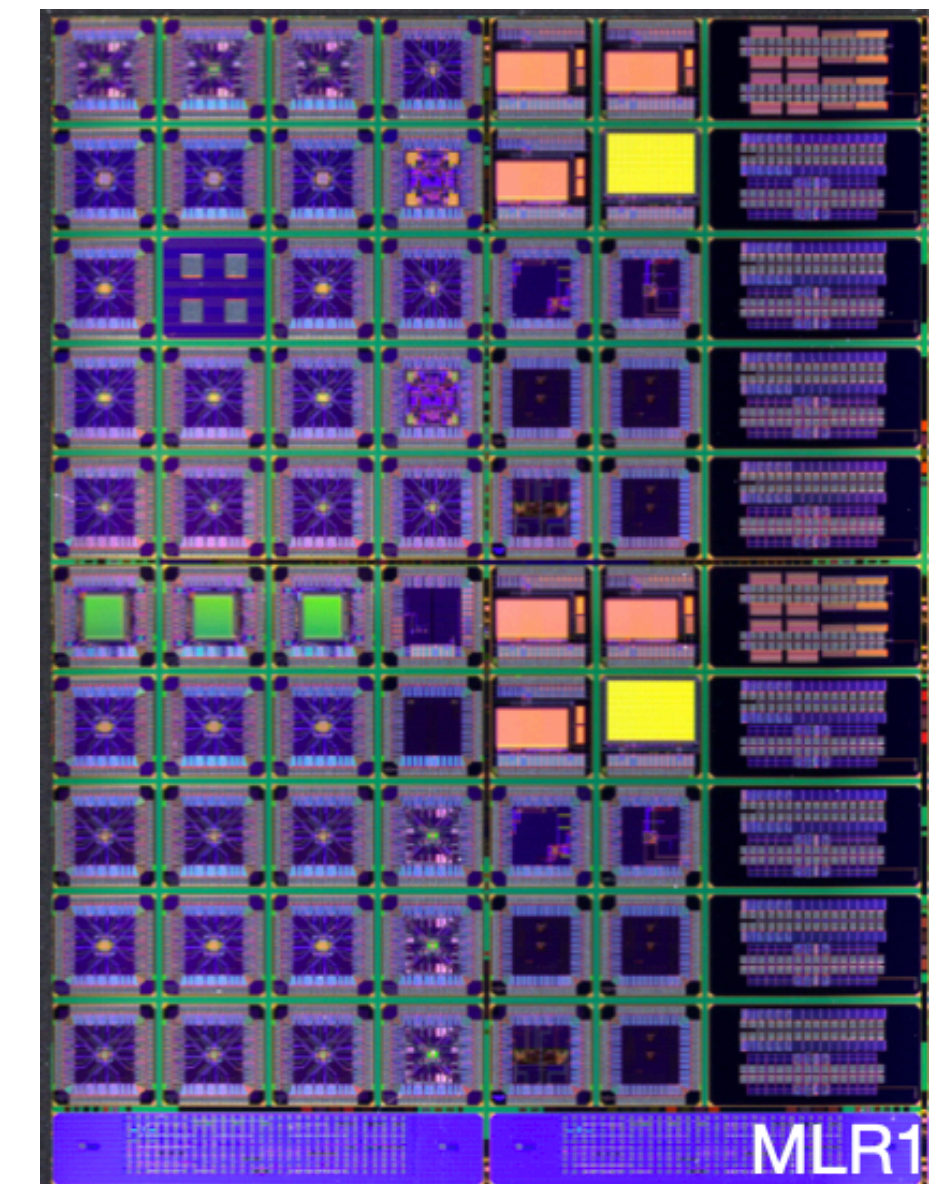
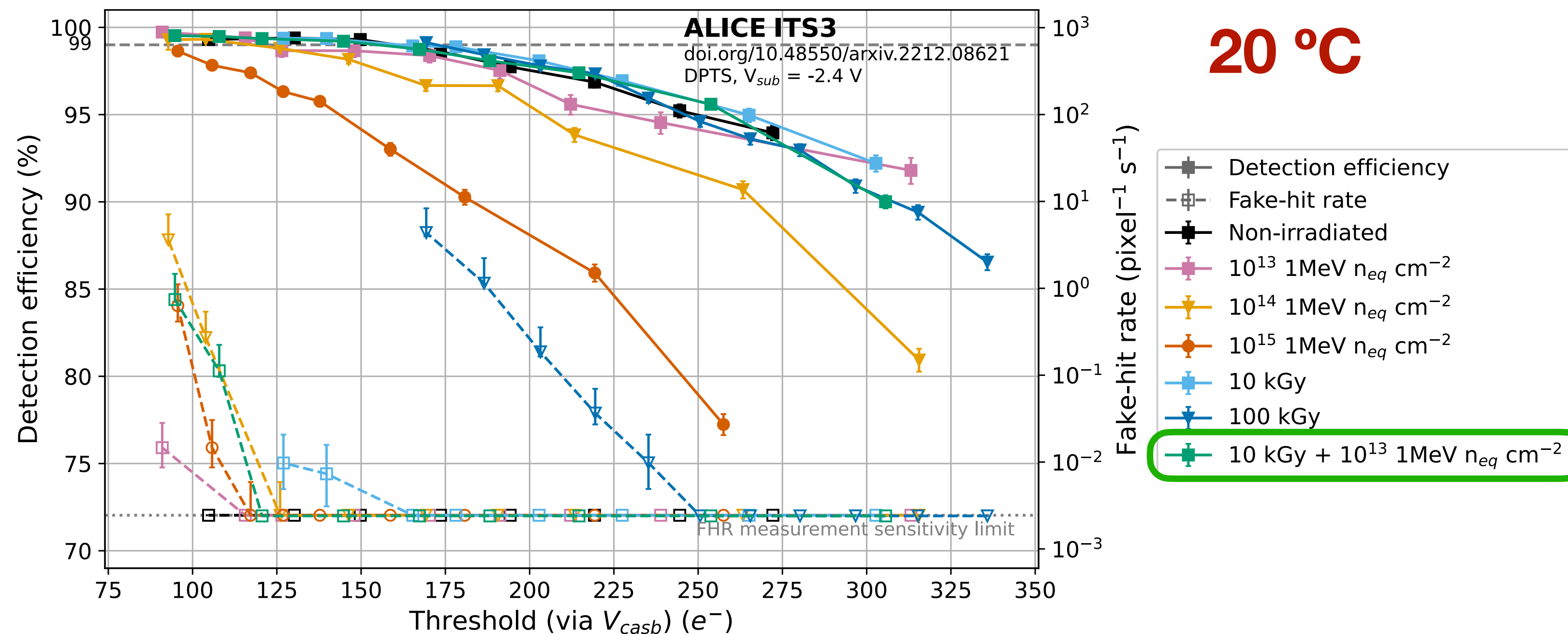




# Sensor technology validation

Tower Partners Semiconductors (TPSCo) **65 nm CMOS imaging technology** result of the effort of **ALICE ITS3** together with **CERN EP R&D**

- **Validated in terms of charge collection efficiency, detection efficiency and radiation hardness**
- Several pixel variants (pitch 10-25  $\mu\text{m}$ ) were tested both in laboratory and in beam tests
- Excellent detection efficiency over large threshold range for the **ITS3 radiation hardness requirement (10 kGy +  $10^{13}$  1MeV  $n_{eq}$  /cm<sup>2</sup>)**

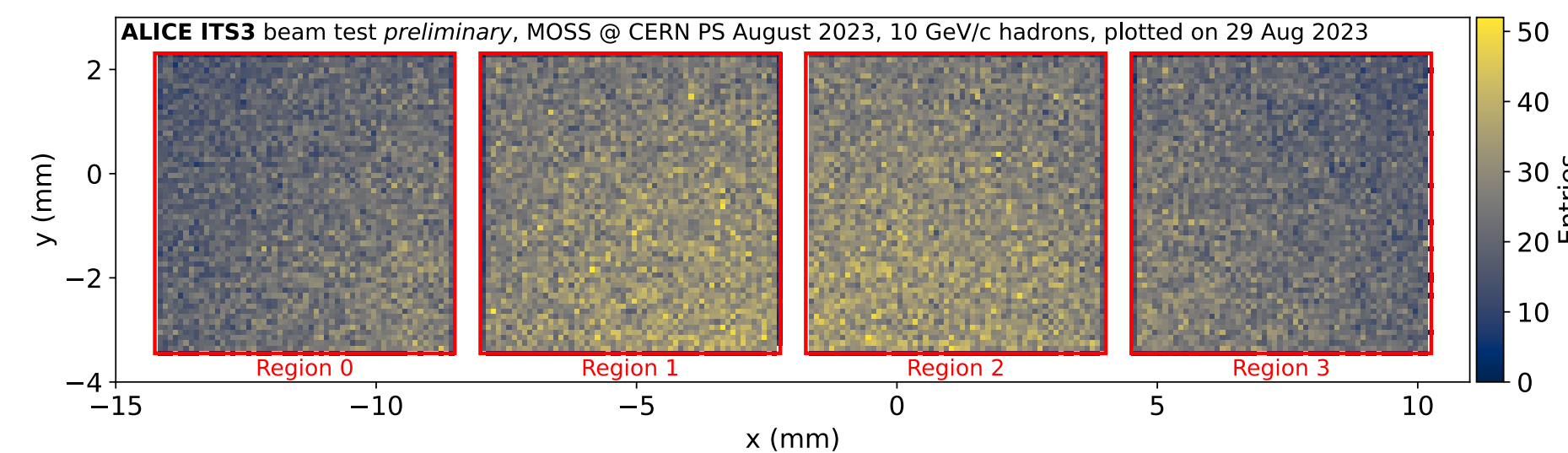
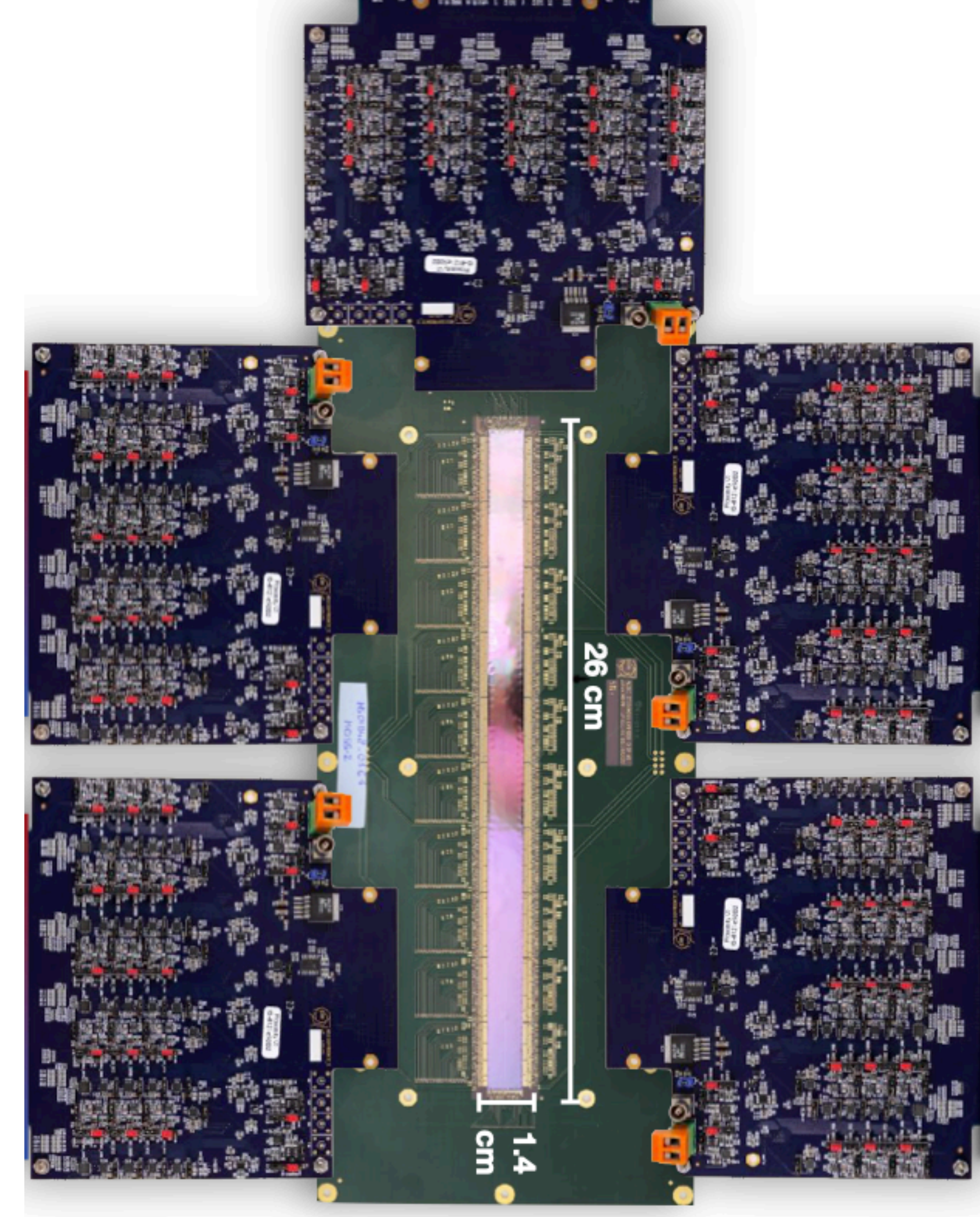
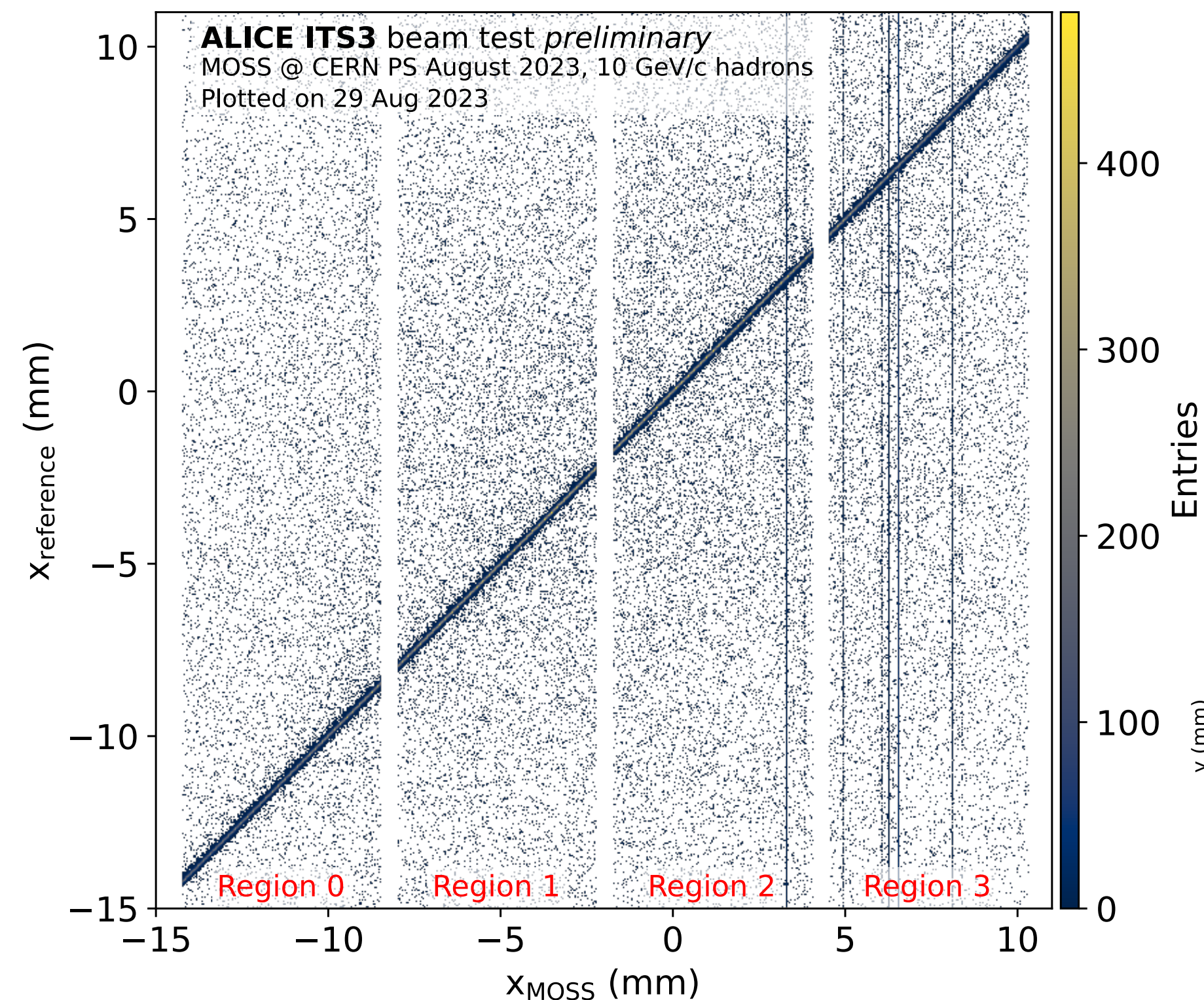
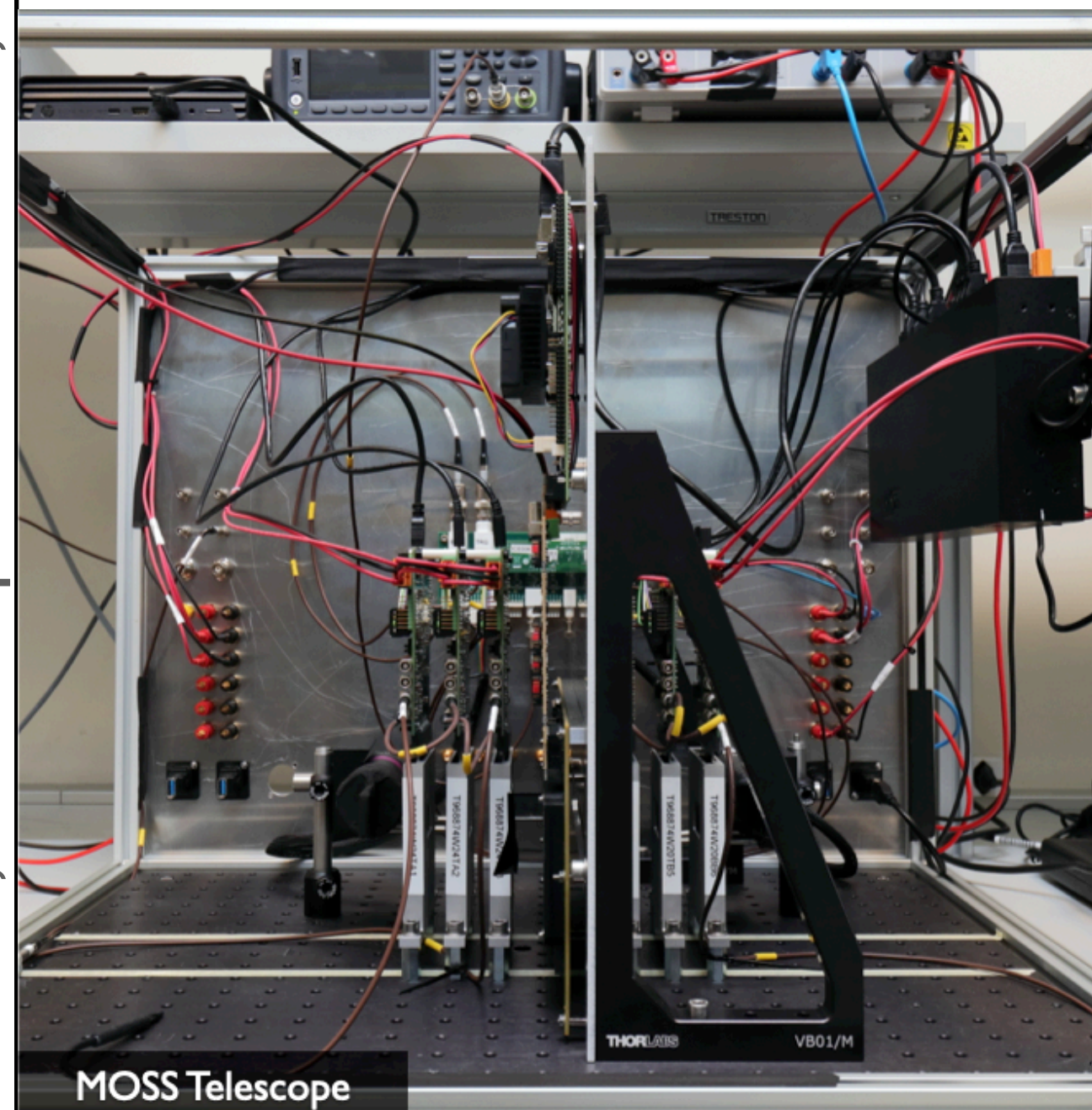




# Sensor stitching

First stitched unit **MO**onolithic **S**titched **S**ensor (**MOSS**) received this June:

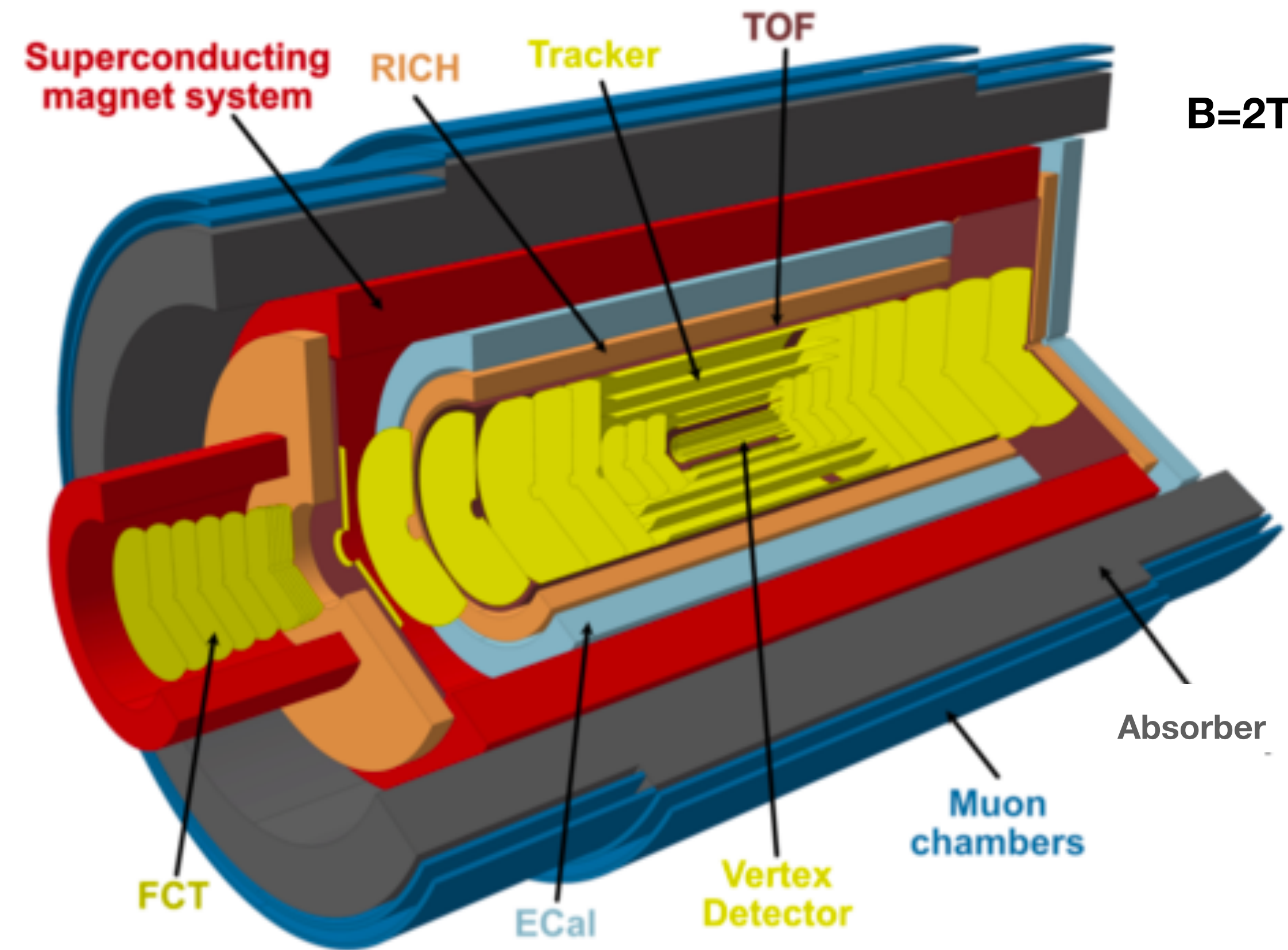
- **Wafer probing and systematic lab tests:** verified all basic functionalities, ongoing full characterization to assess yield of different sensor sections
- **First beam test @CERN PS** in July: system fully functional, analysis in progress





# ALICE 3

- **Compact** and lightweight all-silicon tracker
  - $p_T$  resolution better than 1% @1 GeV/c and ~1-2% over large acceptance
- **Retractable** vertex detector with **excellent pointing resolution**
  - About 3-4  $\mu\text{m}$  @ 1 GeV/c
- **Large acceptance:**  $-4 < \eta < 4$ ,  $p_T > 0.02$  GeV/c
- $e/\pi/K/p$  particle identification over large acceptance
- **Superconducting magnet system**
- **Continuous readout** and online processing
  - Large data sample to access rare signals
- Muon Identification system, large-area ECal for photons and jets, Forward Conversion Tracker for ultra-soft photons



**Letter of Intent:** [CERN-LHCC-2022-009](https://cds.cern.ch/record/2811113/files/CERN-LHCC-2022-009.pdf)

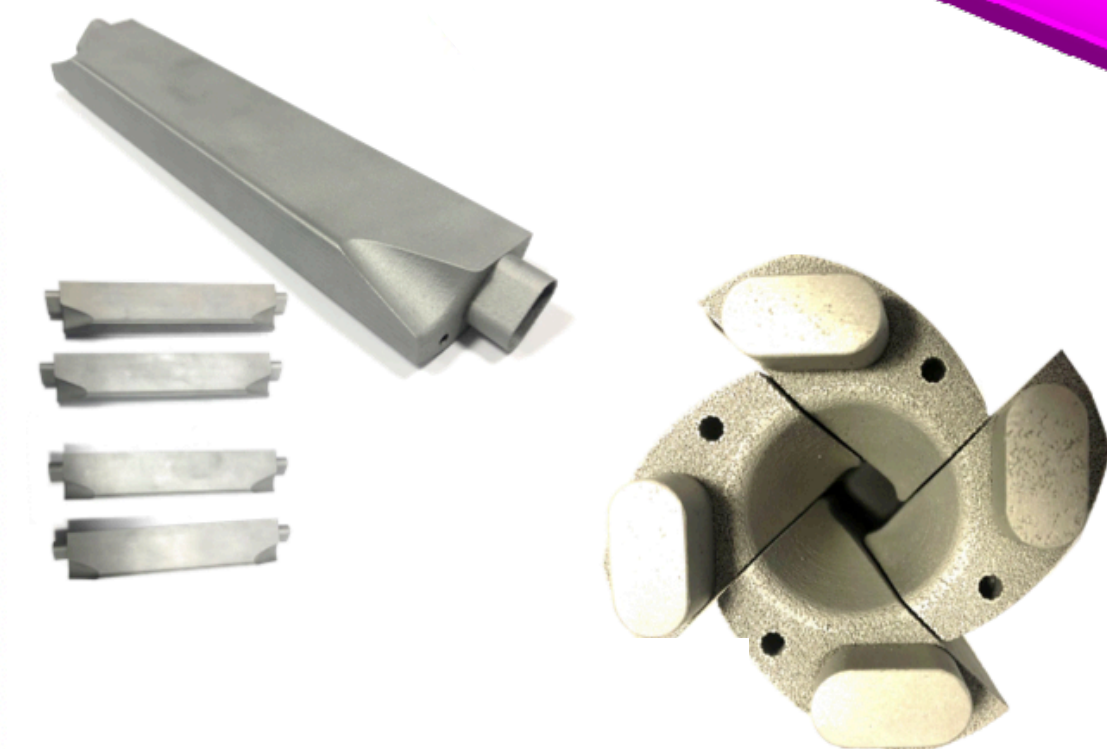
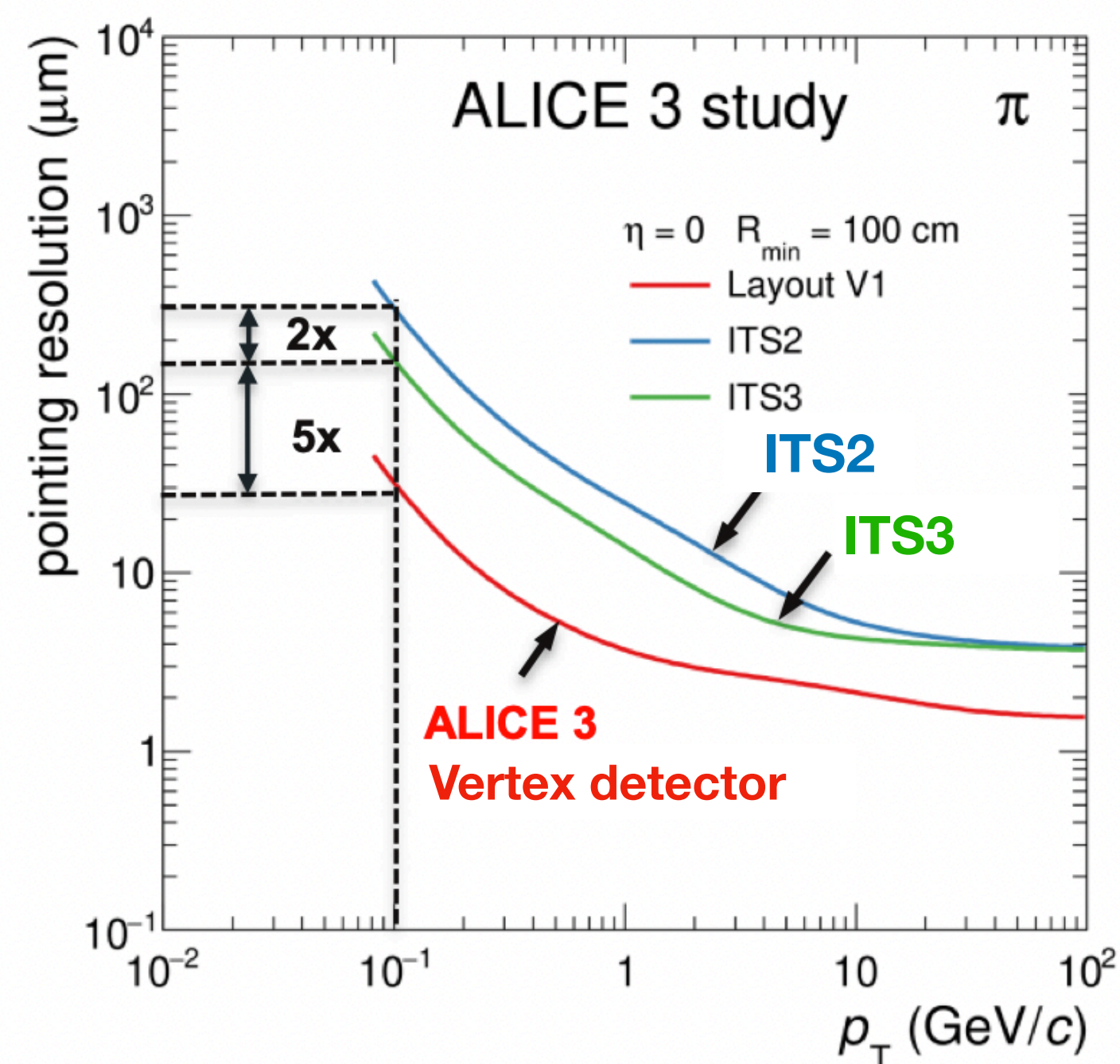
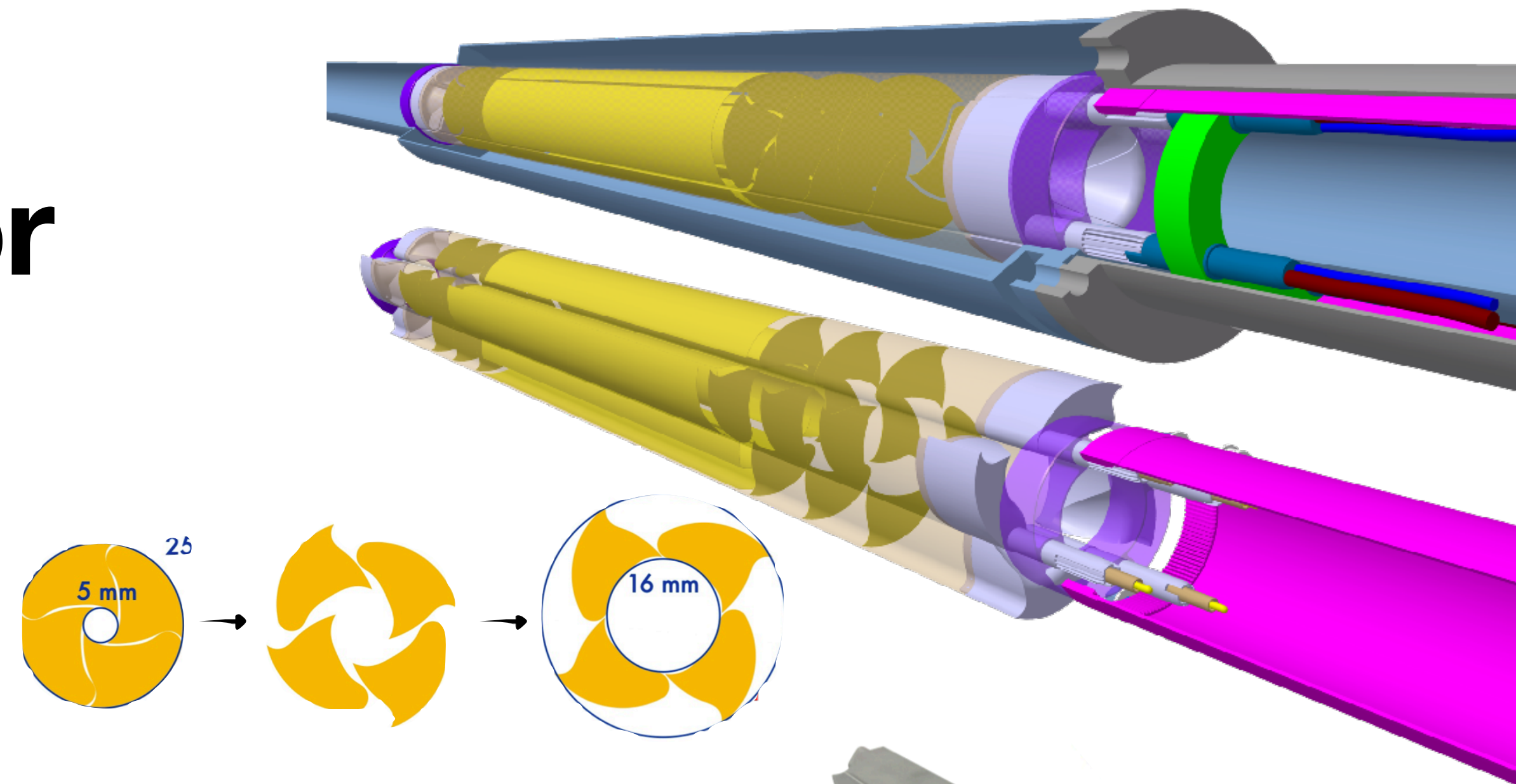


# ALICE 3 - Vertex detector

- 3 layers of wafer-size, ultra-thin, curved, CMOS MAPS **inside the beam pipe** in secondary vacuum
- **Retractable** configuration thanks to **movable petals**: distance of **5 mm** from beam axis for data taking and **16 mm** at beam injection
- Unprecedented spatial resolution:  $\sigma_{\text{pos}} \sim 2.5 \mu\text{m}$
- Extremely low material budget: 0.1% per layer
- Radiation tolerance requirements: 300 Mrad +  $10^{16}$  1MeV neq /cm<sup>2</sup>

ITS3 prototype already achieved  $10^{15}$  1MeV neq /cm<sup>2</sup>

**R&D challenges:** radiation hardness, technology feature size, cooling



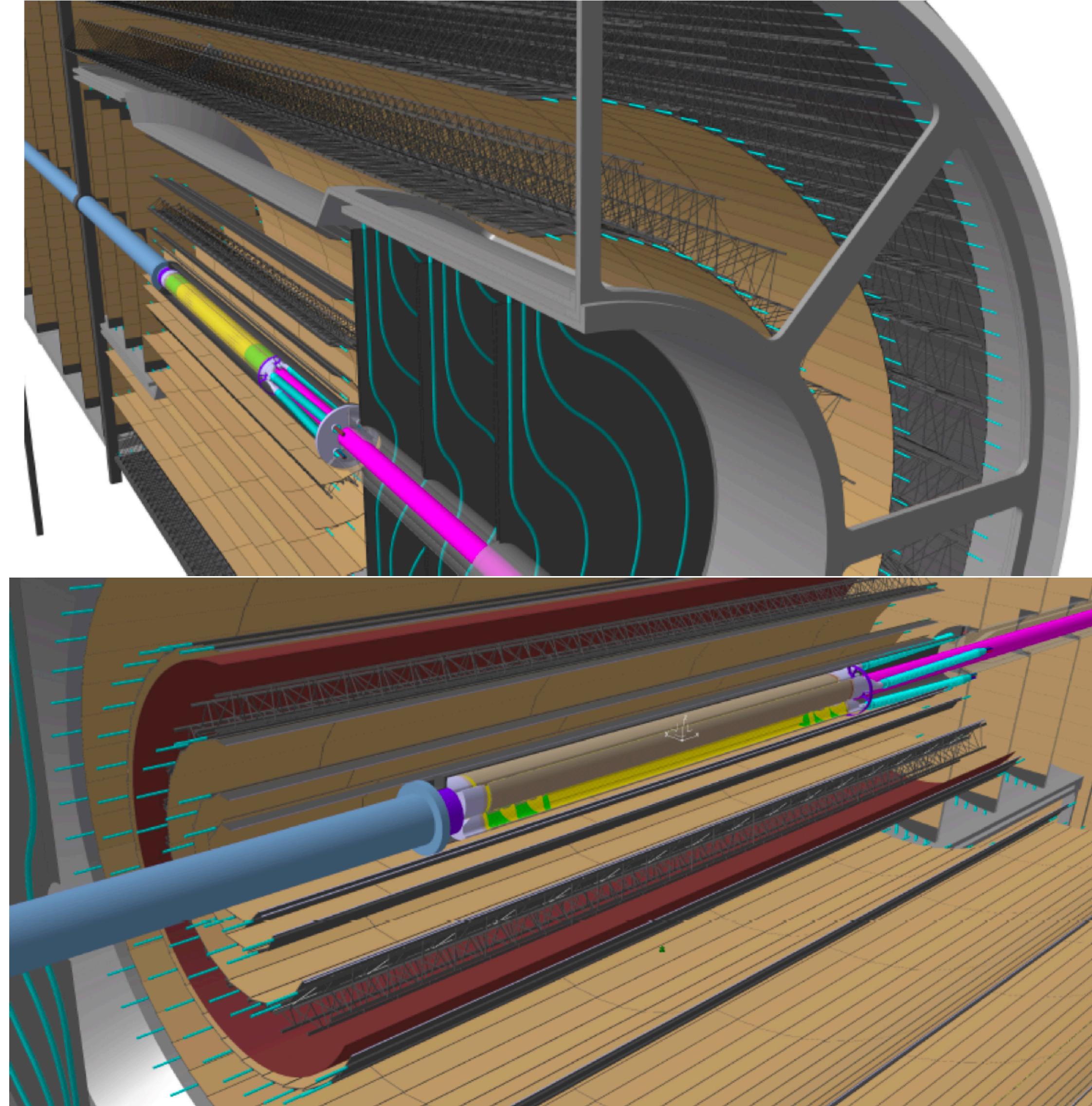
**Bread-Board Model 3 (BBM3)**

3D-printed aluminium petals  
0.5mm wall thickness



# ALICE 3 - Tracker

- 8 + 2 x 9 tracking layers (barrel + disks)
- 60 m<sup>2</sup> silicon pixel detector based on **CMOS MAPS technology**
- Compact: **r<sub>out</sub> ~80 cm**, z<sub>out</sub> ± 4 m
- Large coverage: ± 4  $\eta$
- Time resolution: ~100 ns
- Sensor pixel pitch of ~50  $\mu\text{m}$  for  $\sigma_{\text{POS}} = 10 \mu\text{m}$
- Low power consumption: ~ 20 mW/cm<sup>2</sup>
- Very low material budget: ~1% X<sub>0</sub> per layer



**R&D challenges:** module integration, timing performance and material budget



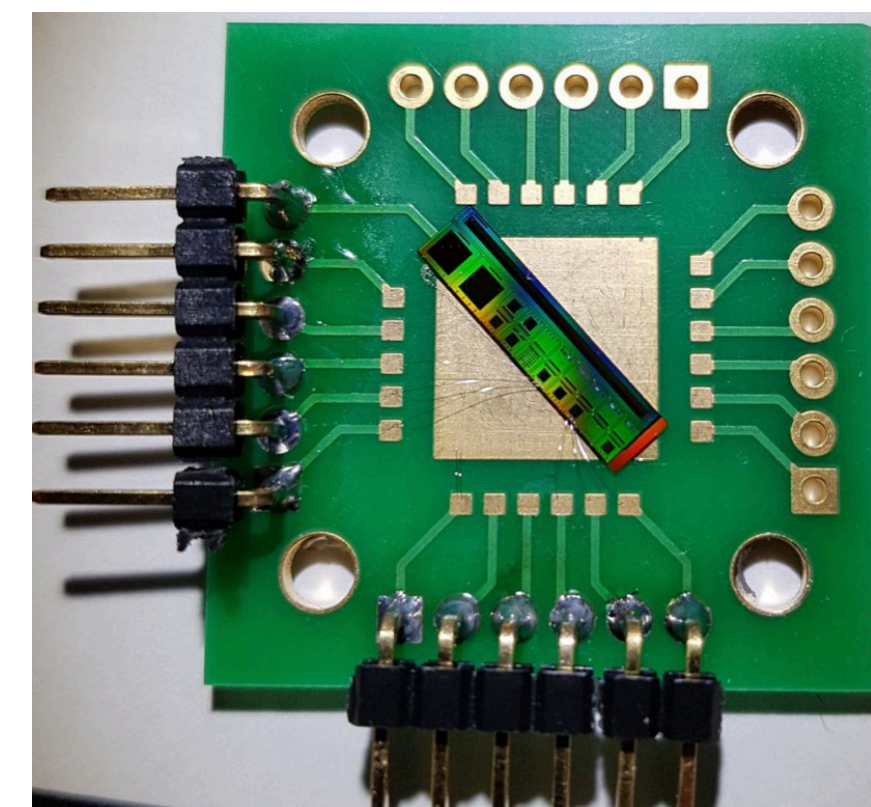
# ALICE 3 - Particle identification - TOF

Time of Flight detectors concept based on **silicon timing sensors**:

- Outer TOF at  $R \approx 85$  cm
- Inner TOF at  $R \approx 19$  cm
- Forward TOF at  $z \approx 405$  cm

Total silicon area  $45 \text{ m}^2$   
Separation up to  $2 \text{ GeV}/c$

**CMOS with gain layer**

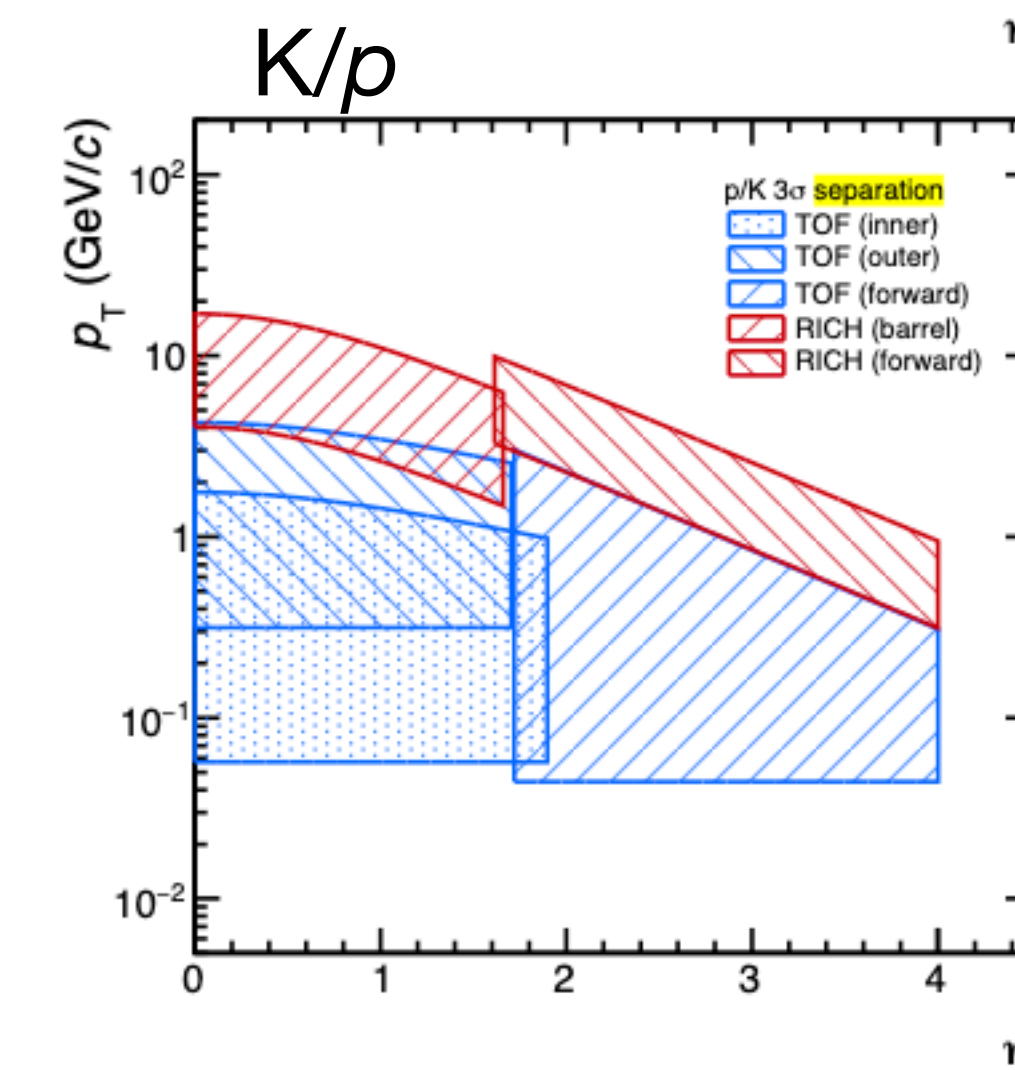
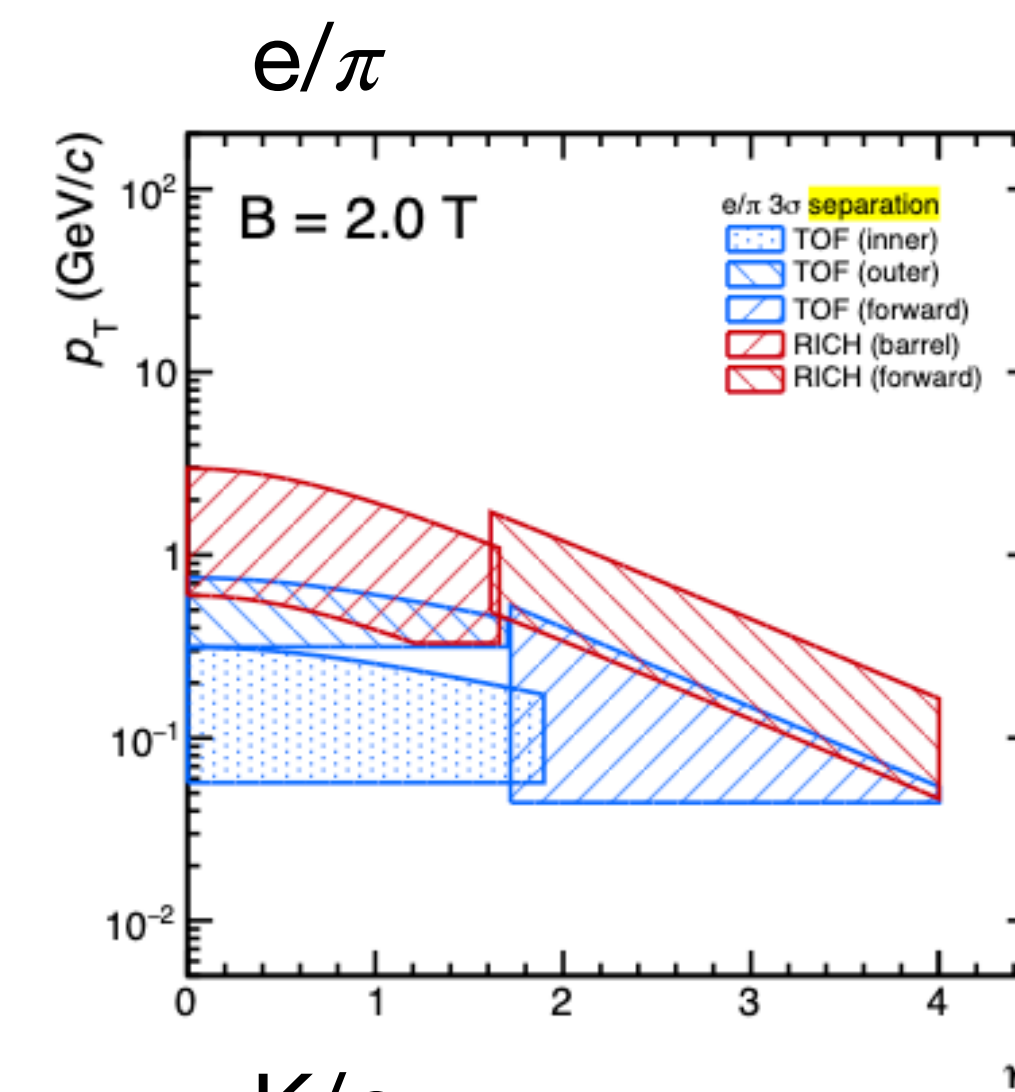
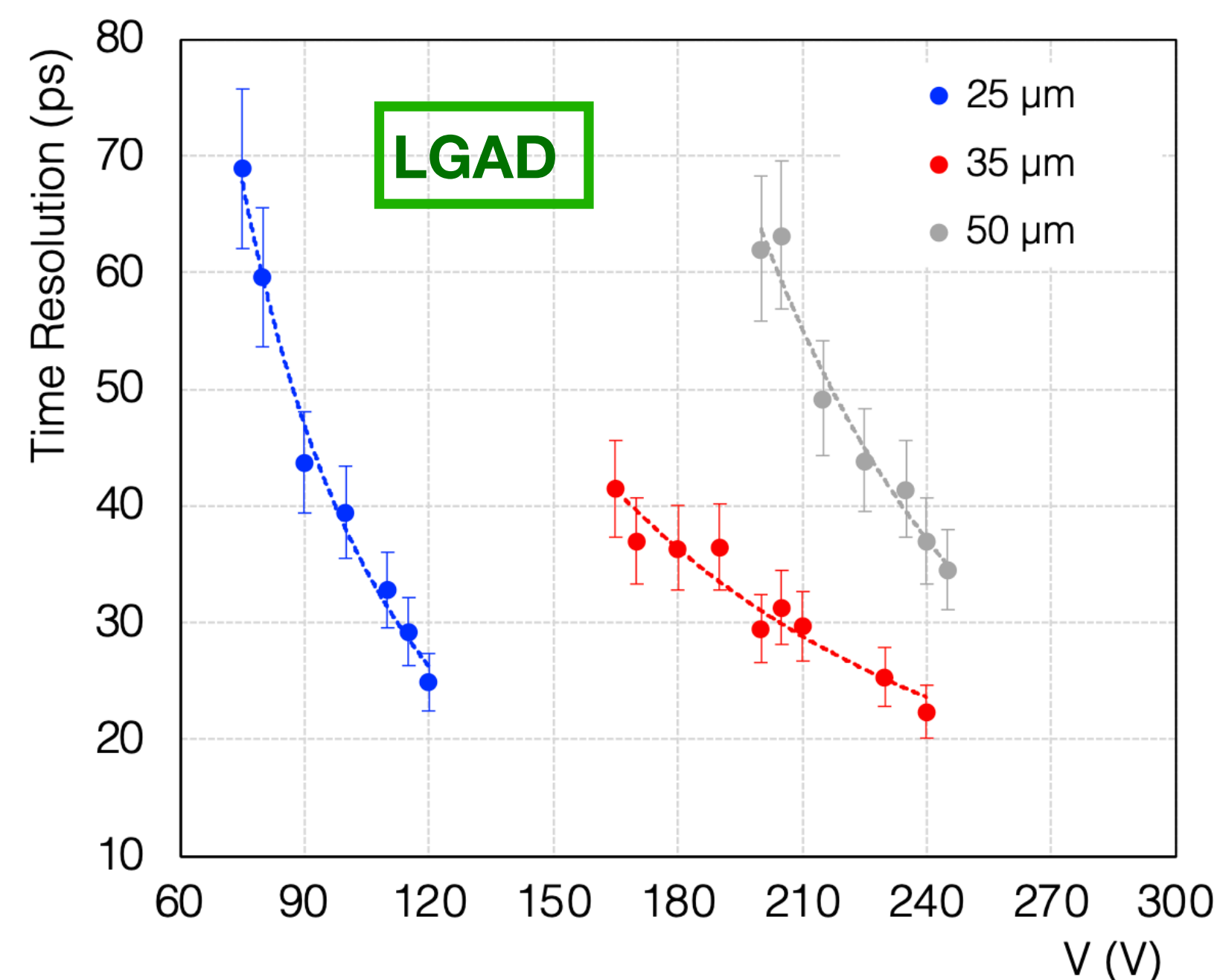


Separation power  $\propto L/\sigma_{TOF}$

- Distance and time resolution are crucial

Silicon timing sensors ( $\sigma_{TOF} \approx 20 \text{ ps}$ ):

- R&D on LGADs and on CMOS with gain layer
- **Test beam for new prototypes in October**





# ALICE 3 - Particle identification - RICH

Complement TOF PID with **Cherenkov detector (RICH) with SiPMs**

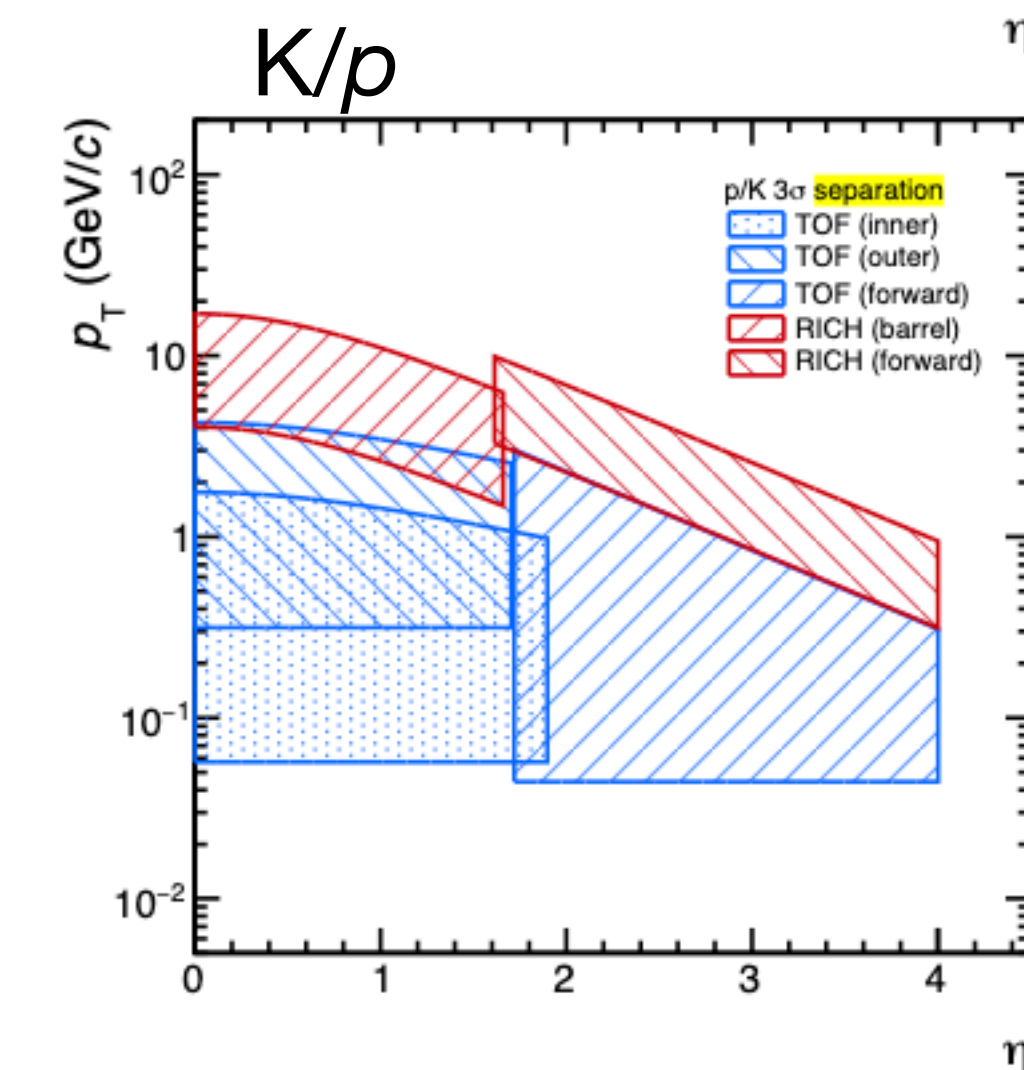
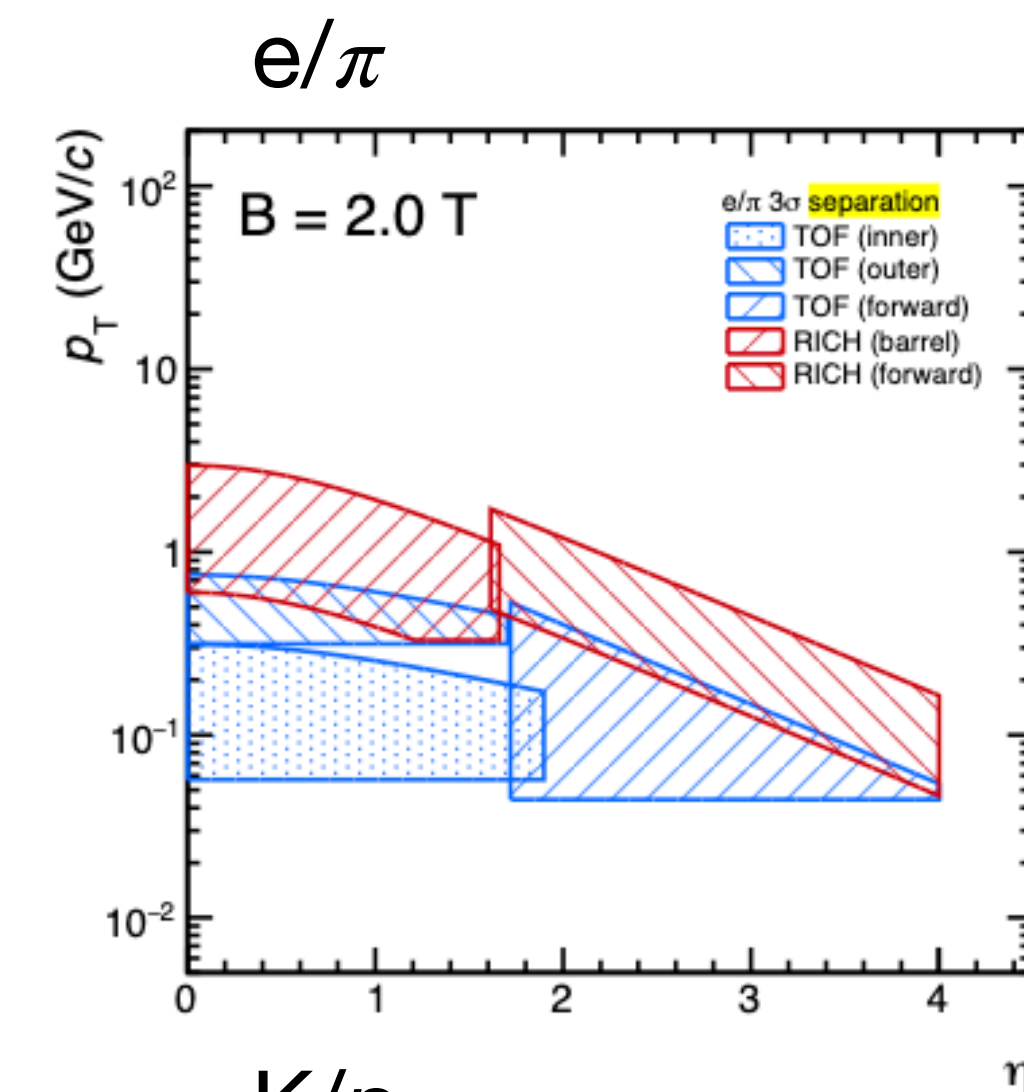
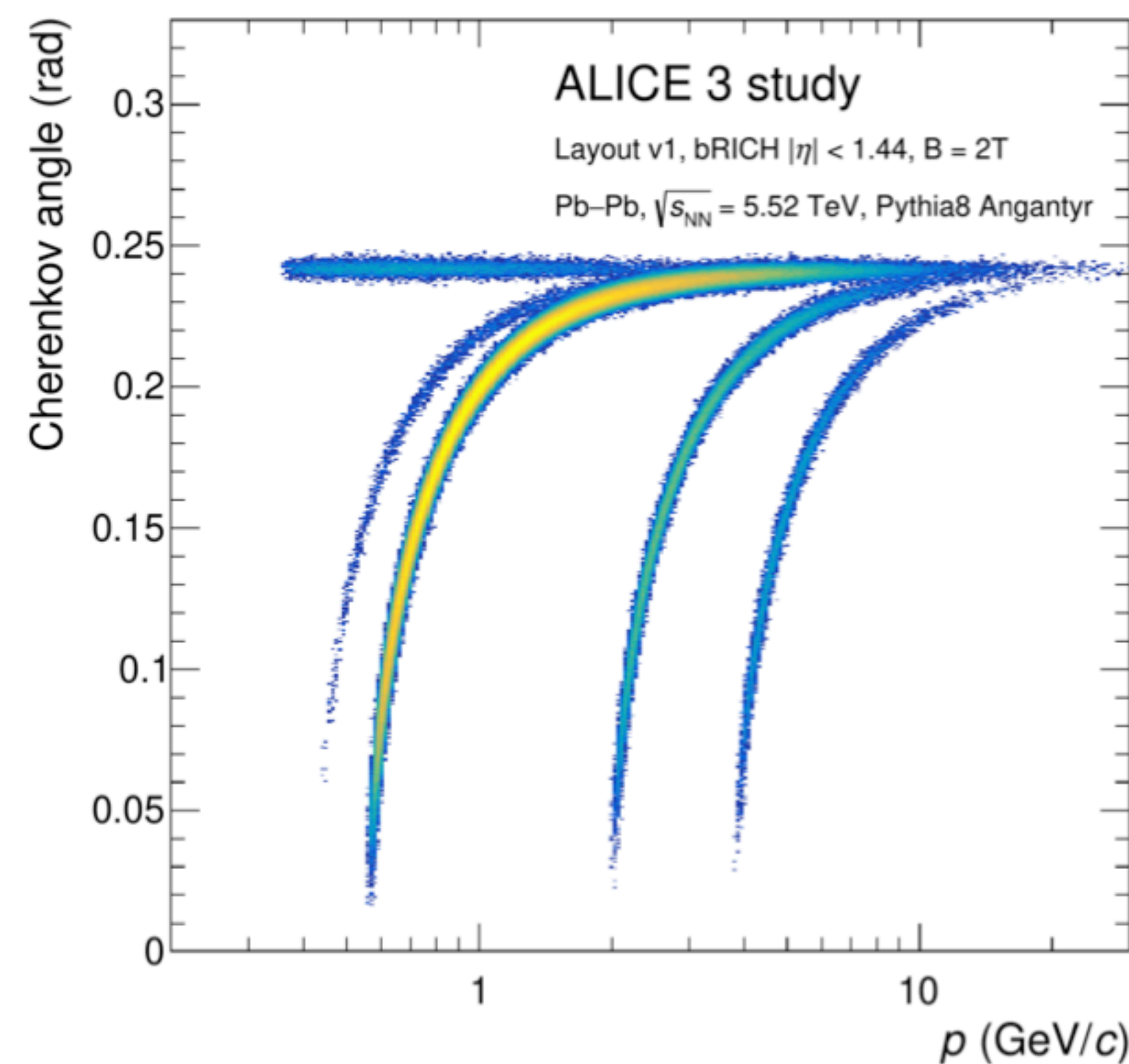
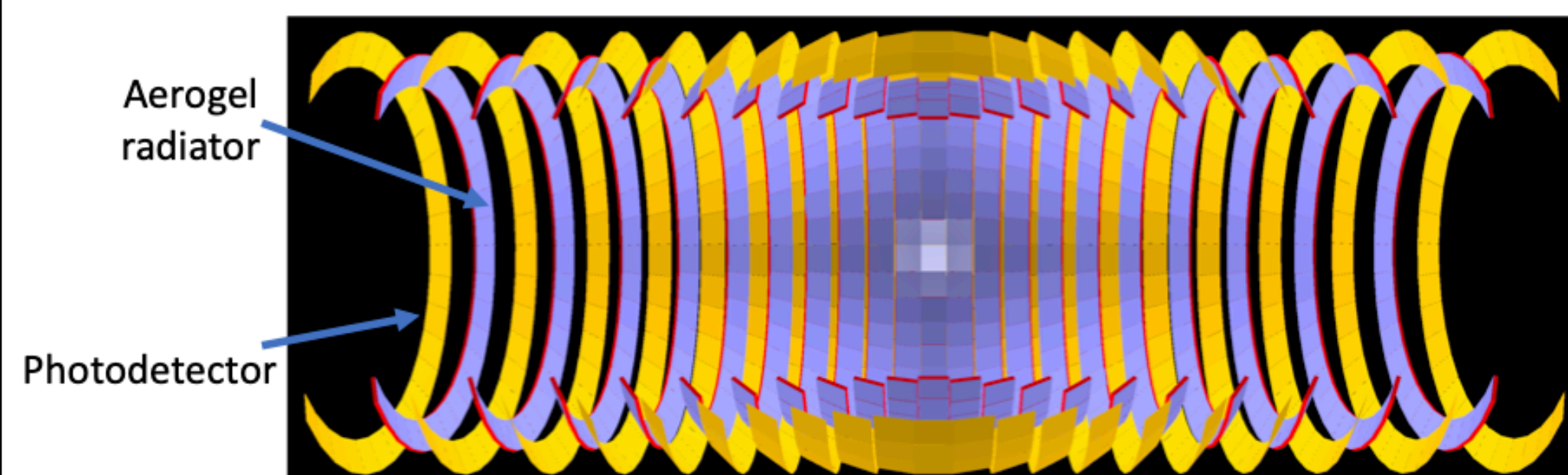
- Extends high  $p_T$  and  $\eta$  coverage of  $e^-$  and hadron ID

Total SiPM area 40 m<sup>2</sup>  
Continuous separation from  
100 MeV/c to 10 GeV/c

Detectors concept (barrel + forward):

- Aerogel radiator
- R&D on monolithic silicon photon sensors

Beam test in October on first prototypes

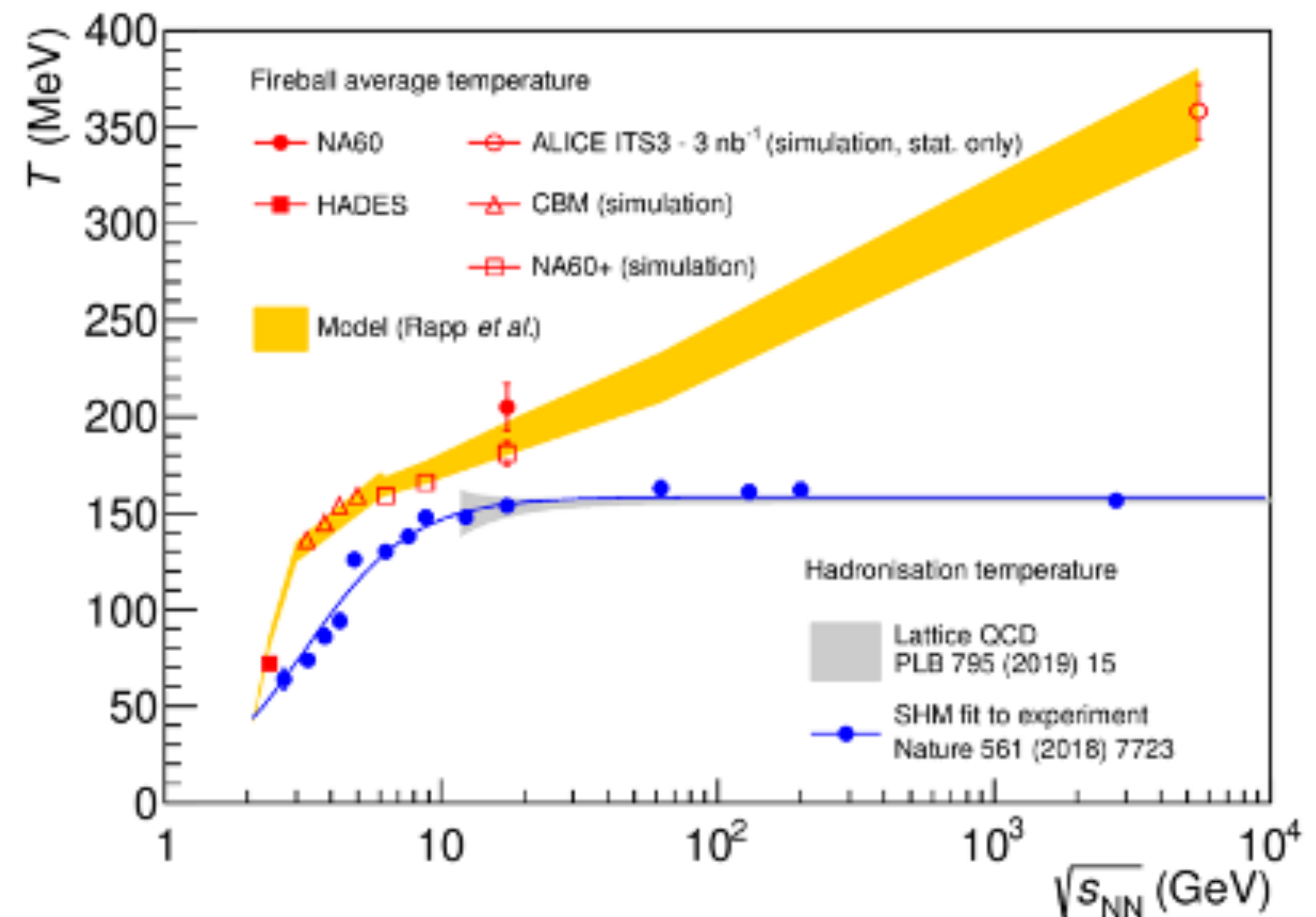
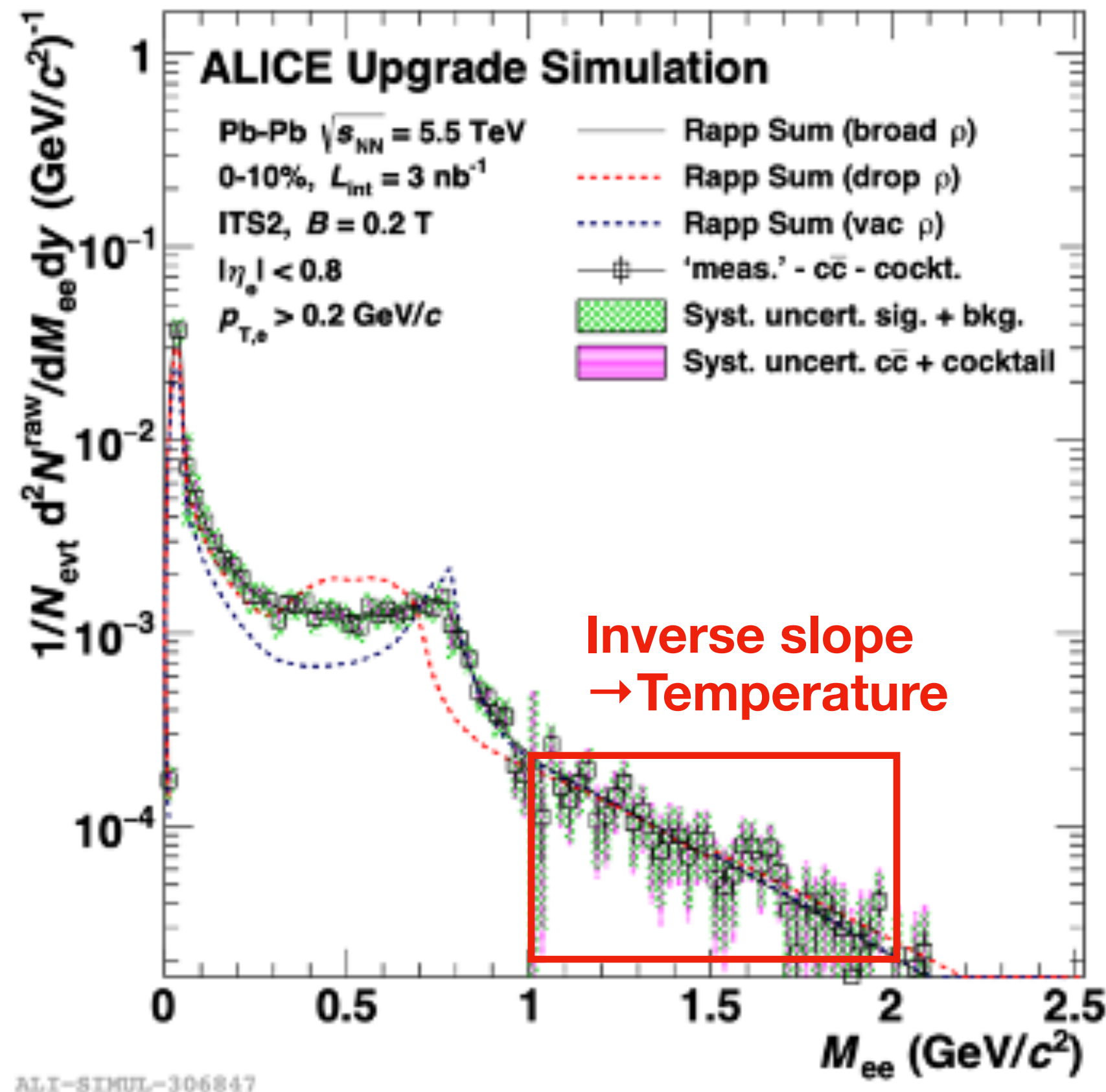




# ITS3 - Physics goals - Dileptons

- **Thermal dileptons**, photons, vector mesons (thermal radiation, chiral symmetry restoration)
  - High precision measurement of temperature in mass region  $1 < M_{ee} < 2 \text{ GeV}/c^2$

**ITS3  
performance**



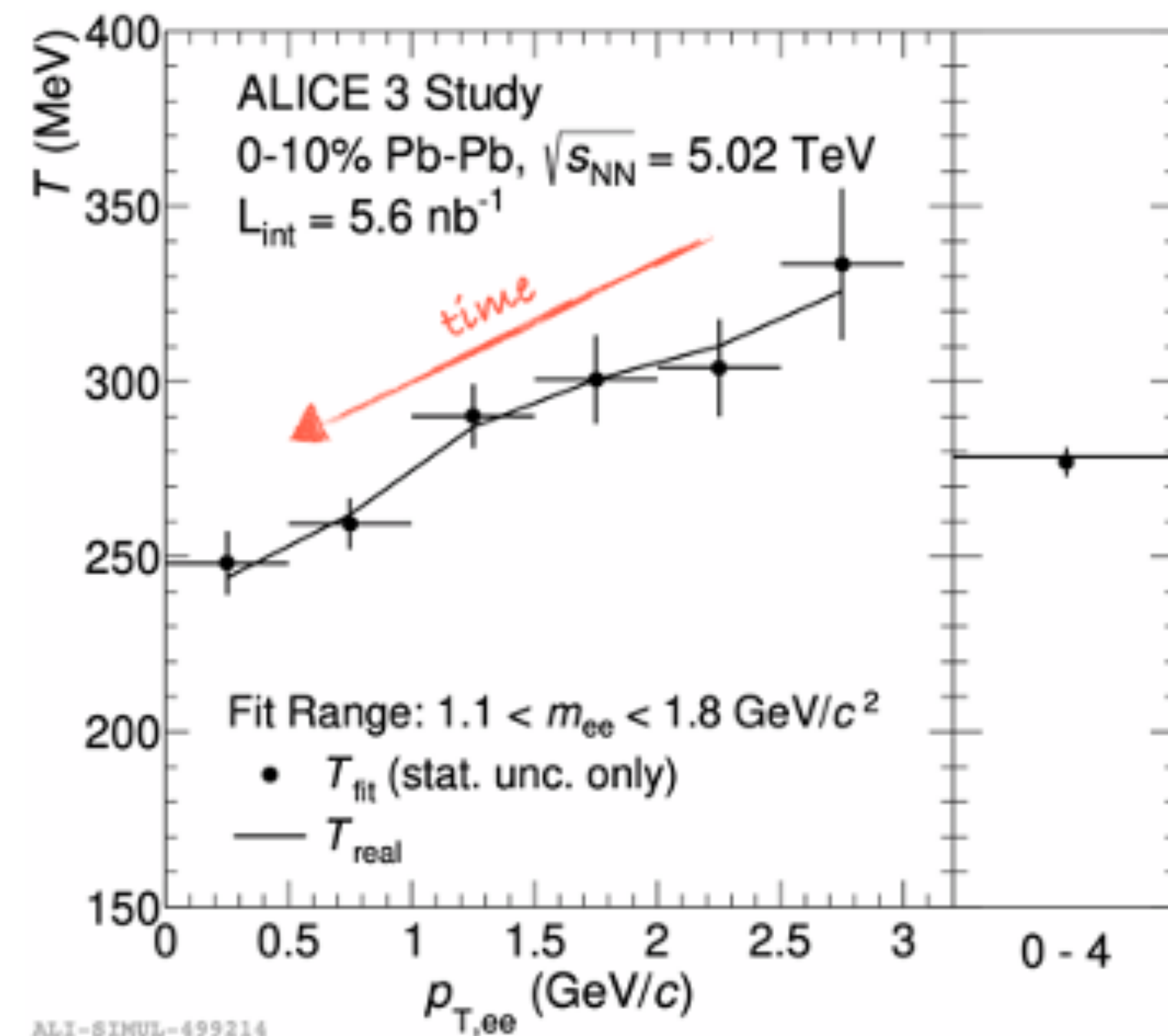
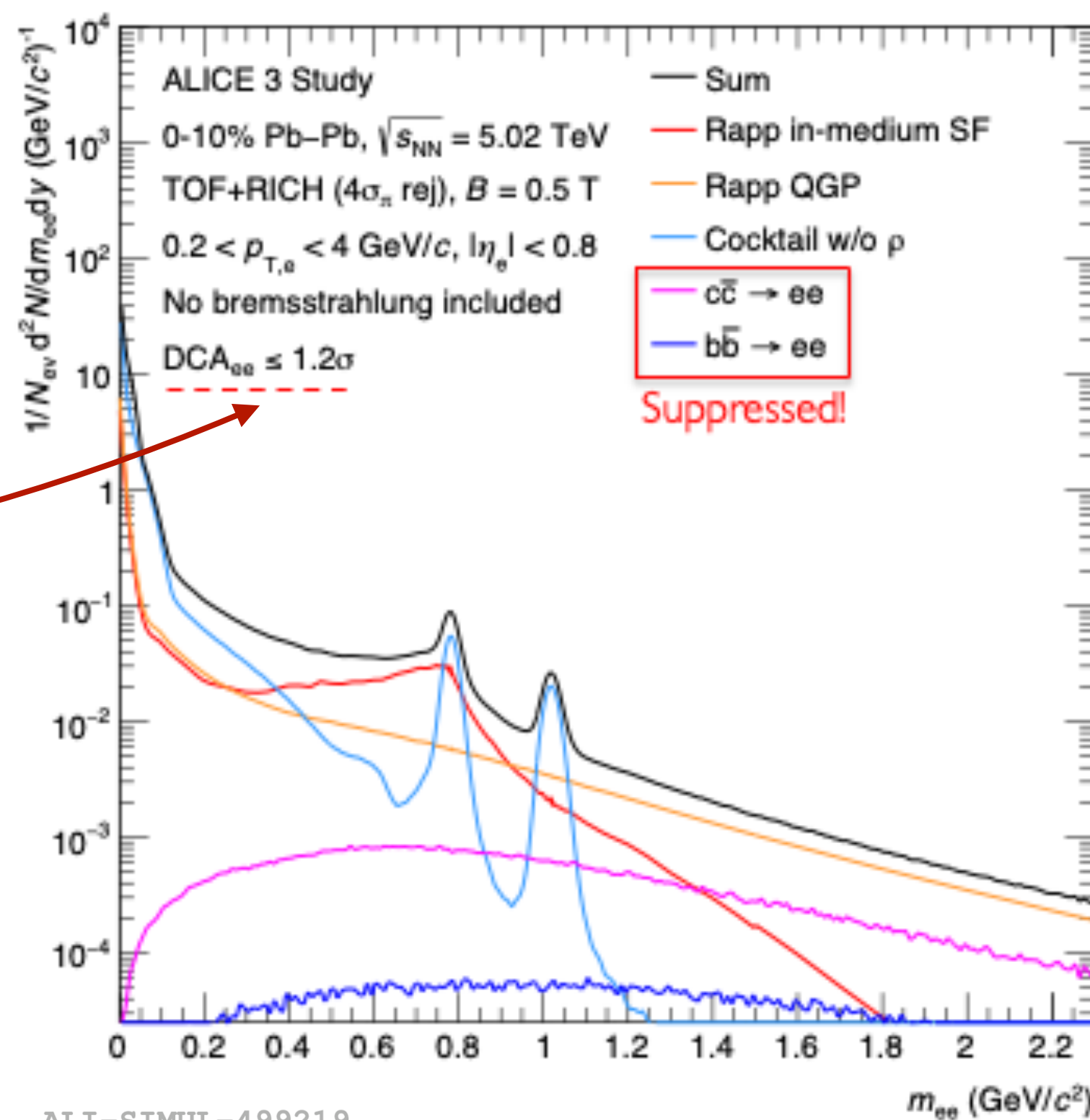
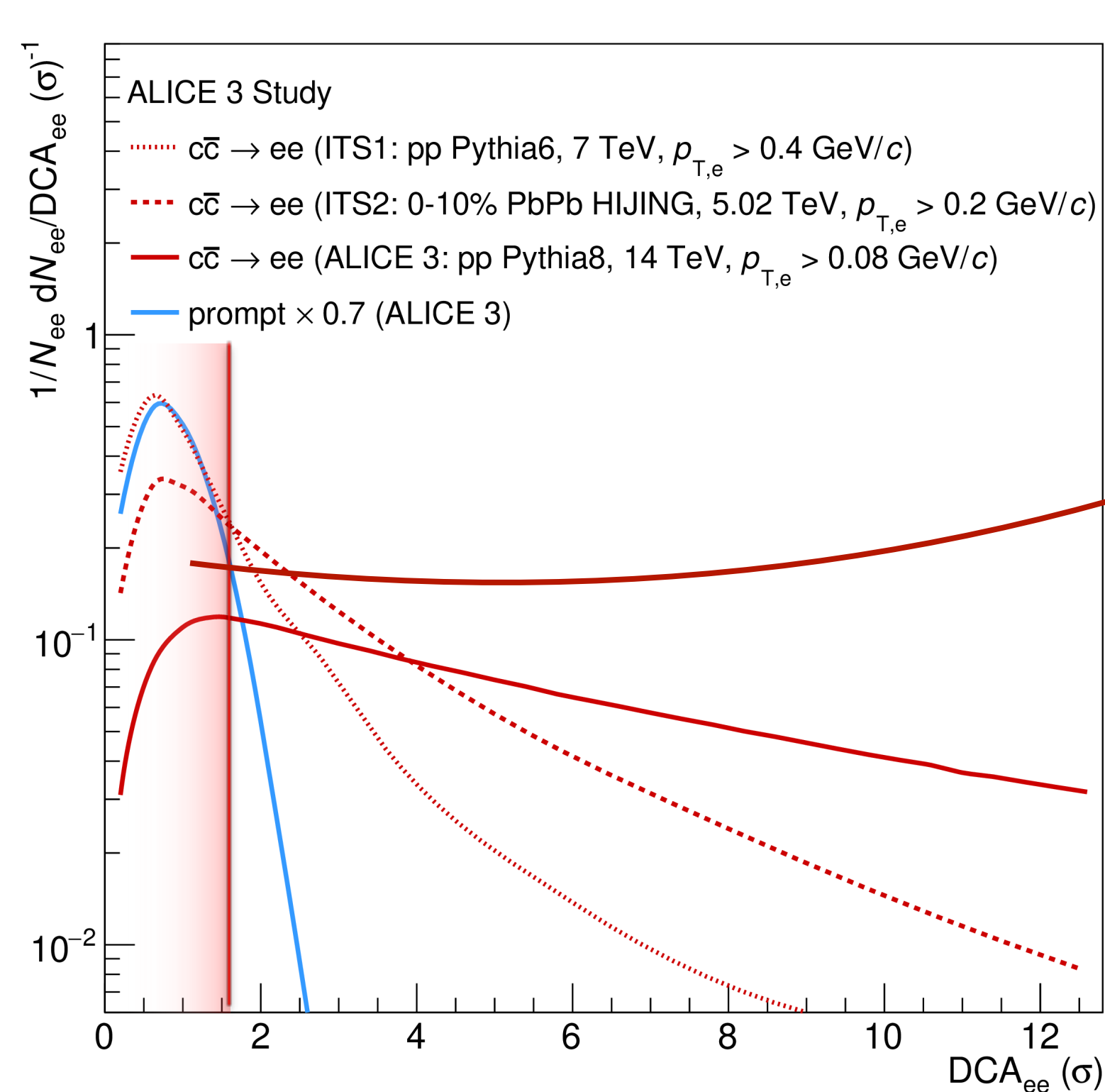
T. Galatyuk, [https://github.com/tgalatyuk/QCD\\_caloric\\_curve](https://github.com/tgalatyuk/QCD_caloric_curve)



# ALICE3 - Physics goals - Dileptons

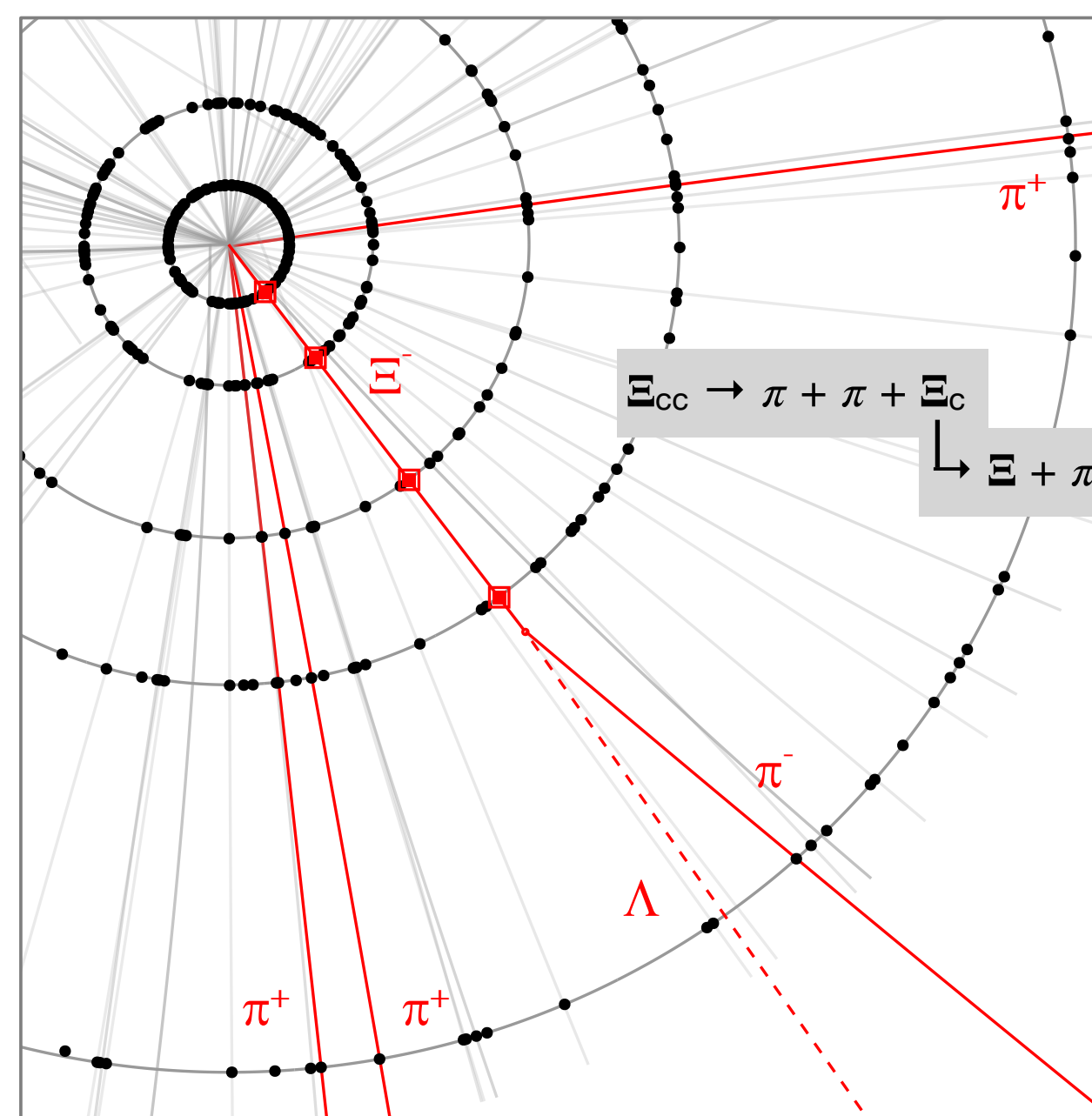
- ALICE 3 high precision tracking results in an unprecedented HF rejection and low- $p_T$  electron ID  
→ background suppression allows a very precise temperature measurement
- Differential analysis in  $p_{T,ee}$ : **only** accessible with ALICE 3

[See more details Sebastian Scheid's poster](#)





- **Heavy flavour** hadrons at low  $p_T$  (charm and beauty interaction and hadronisation in the QGP)
- SHM: hierarchy with  $n$  number of charms ( $g_c^n$ )  $\rightarrow$  multicharm hadrons (e.g.  $\Xi^{++}_{cc}$ )
- Silicon layers inside the beam pipe allow for **direct tracking** of  $\Xi/\Omega$  baryons (**strangeness tracking**)  
 $\rightarrow$  full reconstruction of multi-charm baryon decay vertices





# Summary

Very ambitious program of Upgrades on-going for ALICE:

- **ITS3**: Replacement of inner layers of ITS2 with novel silicon technology to reduce material budget and improve pointing resolution. **R&D is progressing** and showing excellent results
  - **Technology ingredients established**
  - TDR in preparation
- **ALICE 3**: innovative detector concept focusing on silicon technology (vertex detector, tracker, TOF detector and RICH)
  - **R&D activities started** on several strategic areas
  - New observables for low-mass dileptons and HF particles and much more
  - LOI was published on 2022 and Scoping document is foreseen for 2024
  - **ALICE 3 pioneers several R&D directions that can have a broad impact on future HEP experiments** (e.g. EIC, FCC-ee)



The background image shows a large-scale industrial or scientific facility. It features a central, circular, multi-layered structure that appears to be a particle detector or accelerator component. This central structure is surrounded by a complex network of pipes, cables, and structural supports. The overall color scheme is dominated by reds and oranges, with some blue and green accents. The perspective is from a high angle, looking down into the central structure. The text "THANK YOU FOR THE ATTENTION" is overlaid in the center in a bold, white, sans-serif font.

**THANK YOU FOR THE  
ATTENTION**



**BACK-UP**



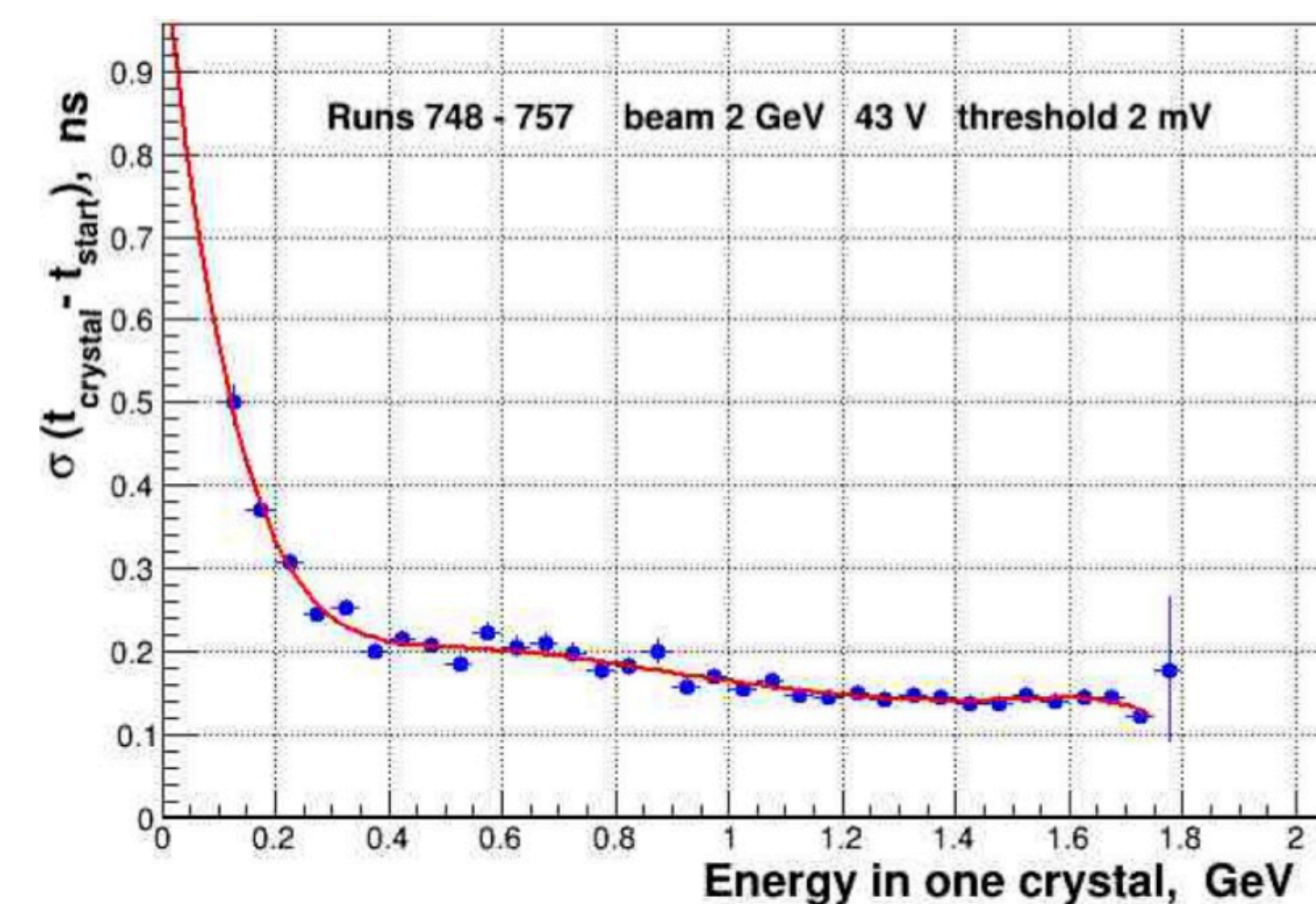
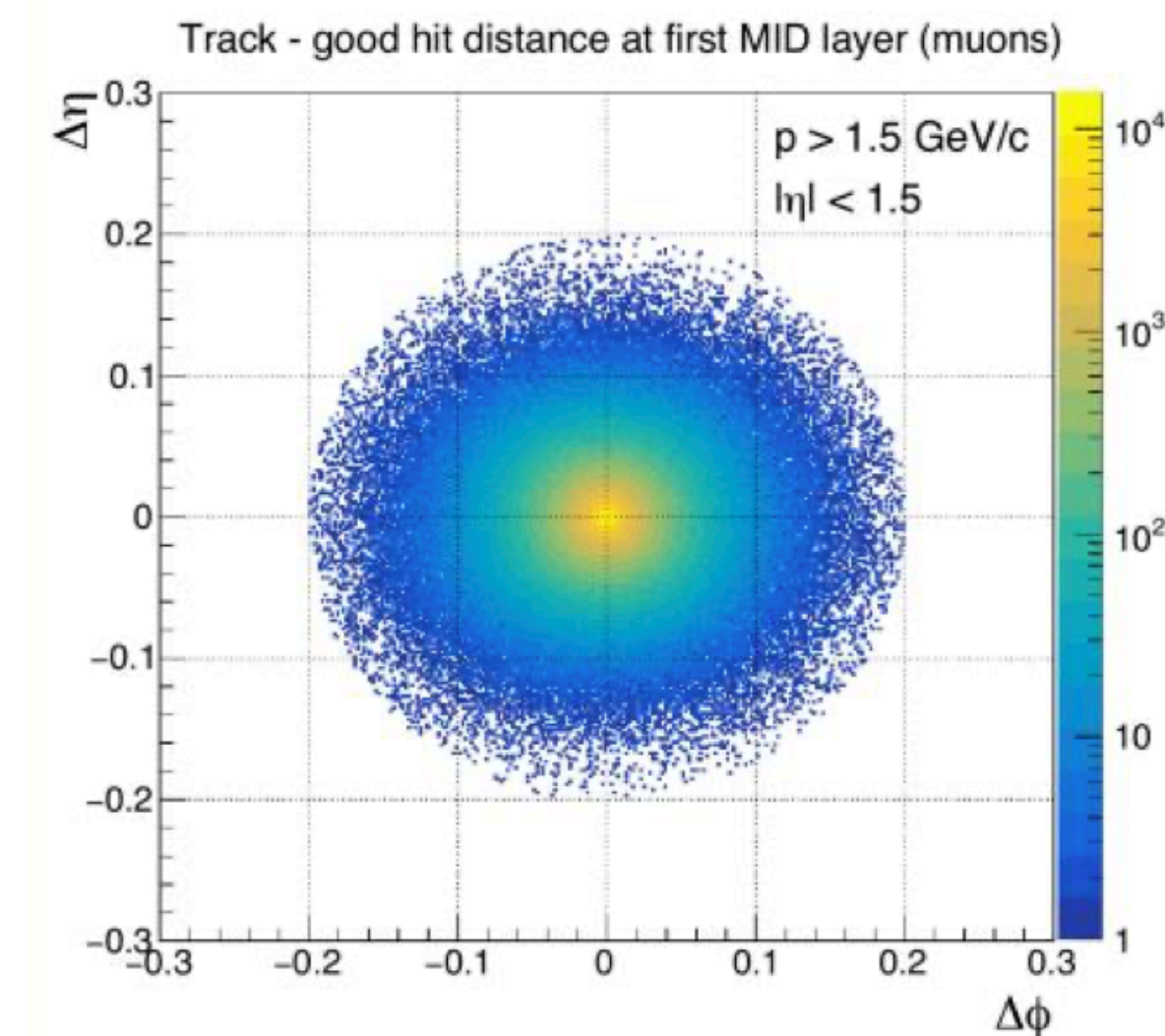
# ALICE 3 - Muon and photon identification

**Muon chambers at central rapidity optimized for reconstruction of charmonia down to  $p_T = 0$  GeV/c**

- ~70 cm non-magnetic steel hadron absorber
- Muon chambers with granularity  $\Delta\eta - \Delta\phi = 0.02 \times 0.02$
- Muon chambers: scintillator bars equipped with wave-length shifting fibers (width 5 cm, gap 20 cm), readout SiPM
- Prototypes tested in beam test in July, analysis on-going

**Large acceptance ECal ( $2\pi$  coverage) critical for measuring P-wave quarkonia and thermal radiation via real photons**

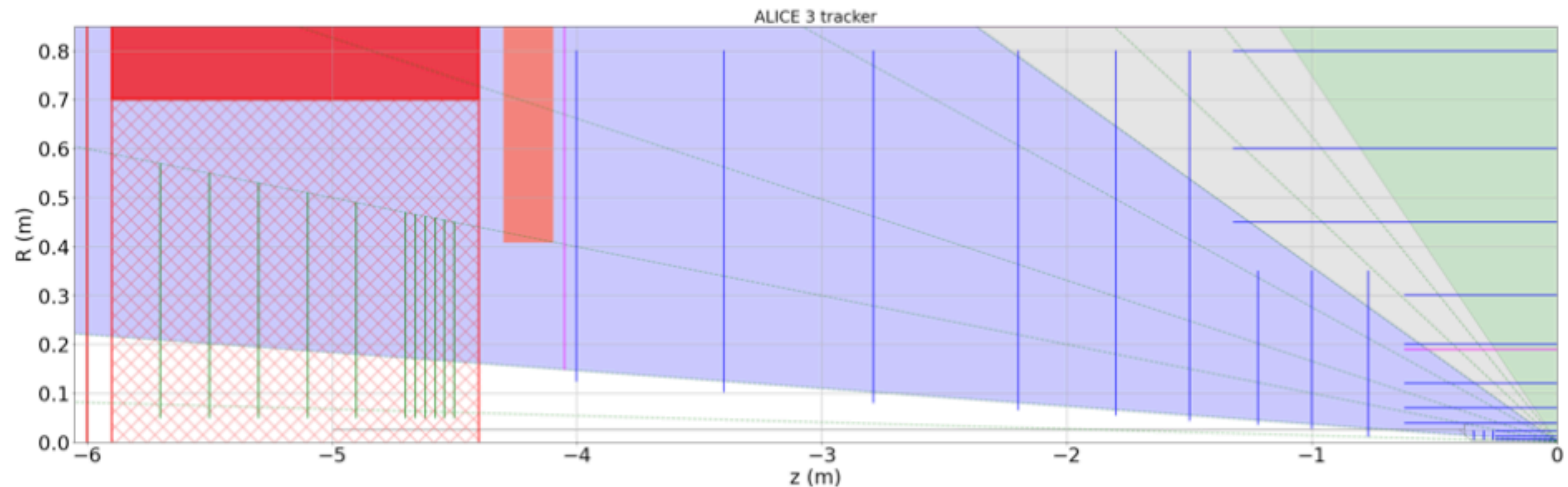
- PbWO<sub>4</sub>-based high energy resolution segment
- Different hybrid photodetectors based on SiPM studied @PS and SPS:  $\sigma_t < 200$  ps (next TB @SPS 2024)





# Forward Conversion Tracker

- **Thin tracking disks** to cover  $3 < \eta < 5$ : few % of a radiation length per layer, position resolution  $< 10 \mu\text{m}$
- **R&D programme** on: large area, thin disks, minimisation of material in front of FCT, operational conditions

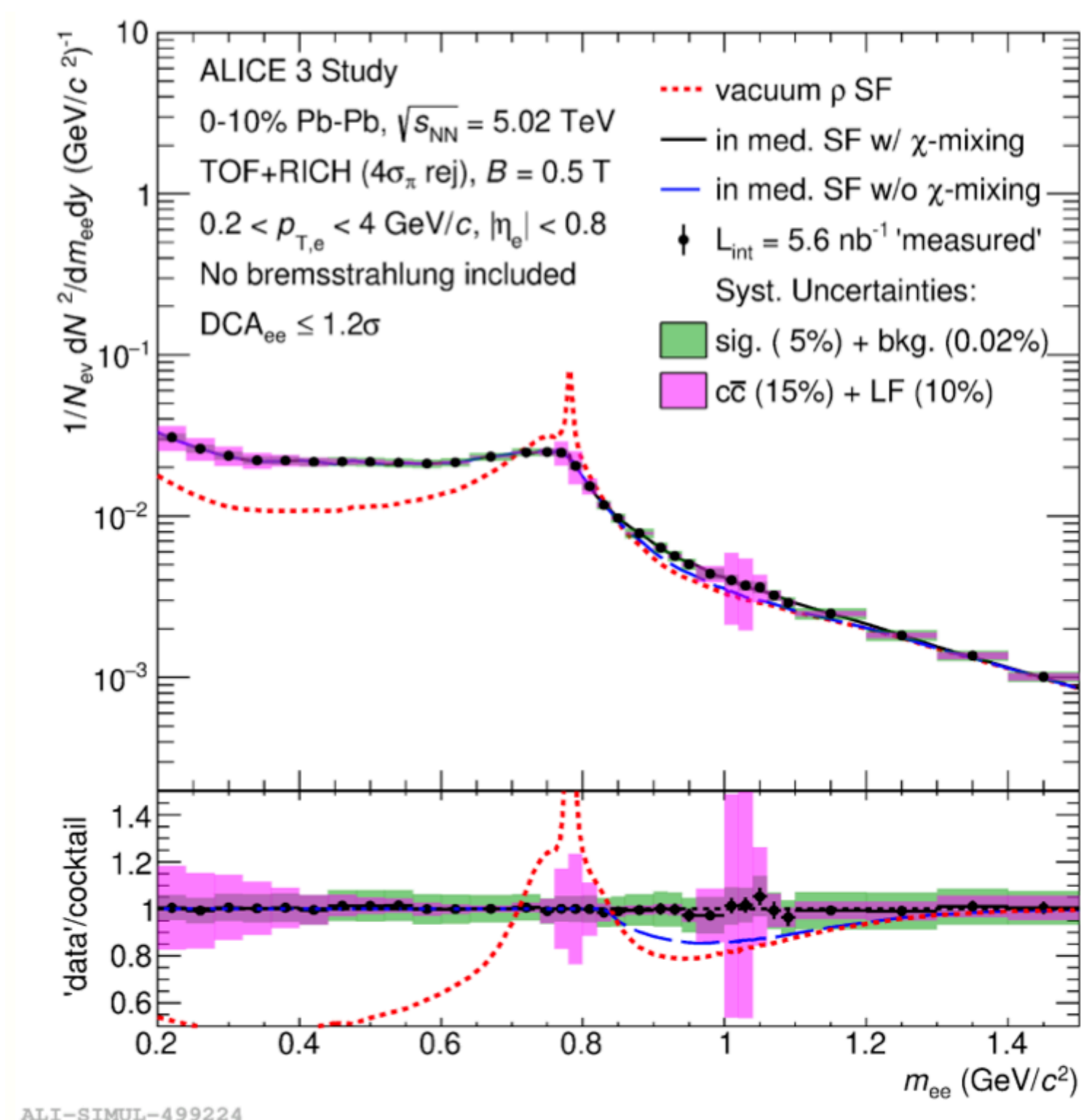
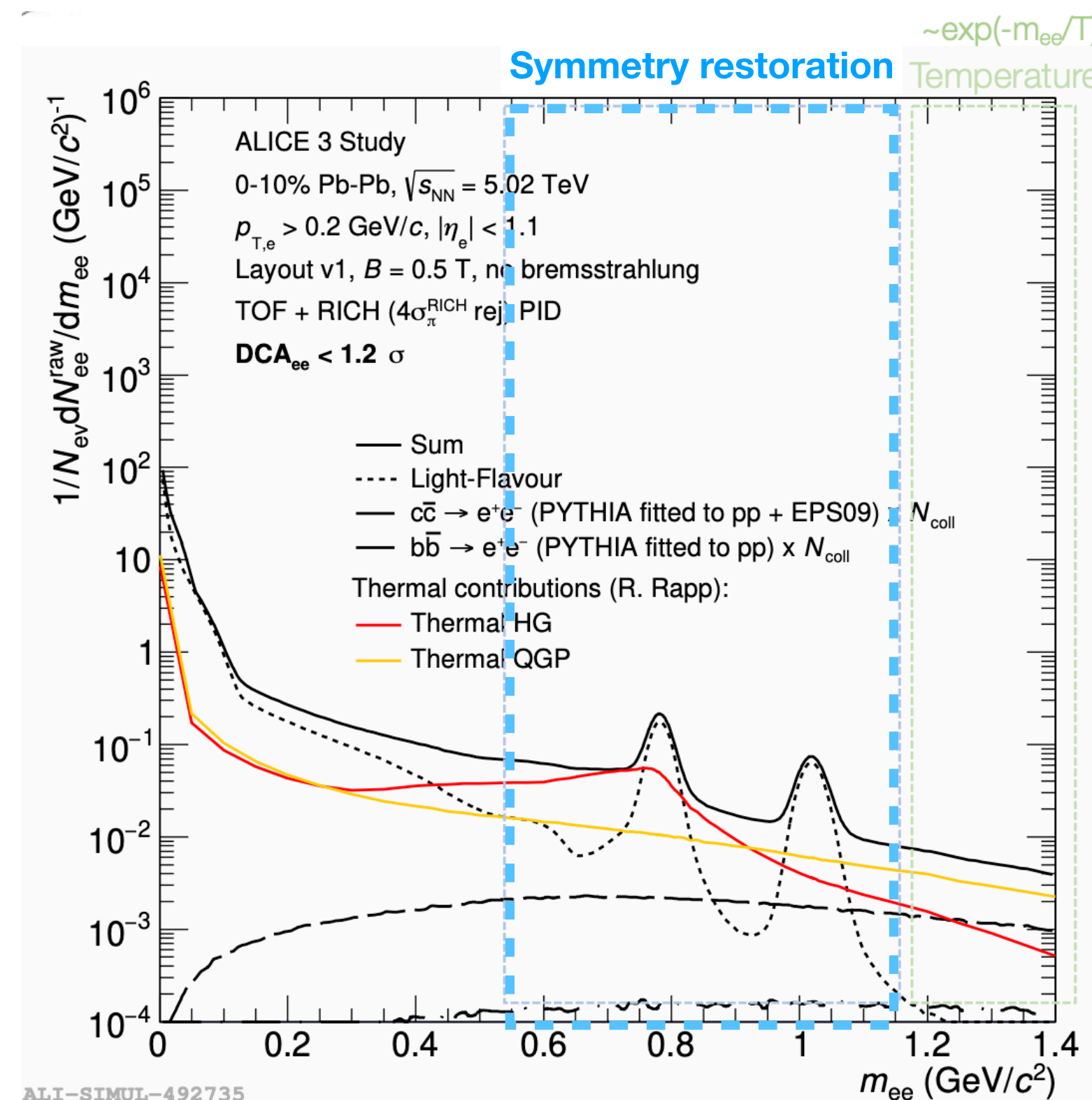




# Chiral symmetry restoration

Dileptons: one observable, multiple physics topics (not only precision measurement of temperature)

- $\rho$  spectral shape (broadening or dropping mass) sensitive to in-plasma **chiral symmetry restoration** (sensitive to  $\rho$ - $a_1$  mixing)
- Statistical and systematic uncertainties will allow to measure the  $\rho$  spectral function with unprecedented precision





# Colliding systems

Quantity	pp	O–O	Ar–Ar	Ca–Ca	Kr–Kr	In–In	Xe–Xe	Pb–Pb
$\sqrt{s_{NN}}$ (TeV)	14.00	7.00	6.30	7.00	6.46	5.97	5.86	5.52
$L_{AA}$ (cm <sup>-2</sup> s <sup>-1</sup> )	$3.0 \times 10^{32}$	$1.5 \times 10^{30}$	$3.2 \times 10^{29}$	$2.8 \times 10^{29}$	$8.5 \times 10^{28}$	$5.0 \times 10^{28}$	$3.3 \times 10^{28}$	$1.2 \times 10^{28}$
$\langle L_{AA} \rangle$ (cm <sup>-2</sup> s <sup>-1</sup> )	$3.0 \times 10^{32}$	$9.5 \times 10^{29}$	$2.0 \times 10^{29}$	$1.9 \times 10^{29}$	$5.0 \times 10^{28}$	$2.3 \times 10^{28}$	$1.6 \times 10^{28}$	$3.3 \times 10^{27}$
$\mathcal{L}_{AA}^{\text{month}}$ (nb <sup>-1</sup> )	$5.1 \times 10^5$	$1.6 \times 10^3$	$3.4 \times 10^2$	$3.1 \times 10^2$	$8.4 \times 10^1$	$3.9 \times 10^1$	$2.6 \times 10^1$	5.6
$\mathcal{L}_{NN}^{\text{month}}$ (pb <sup>-1</sup> )	505	409	550	500	510	512	434	242
$R_{\text{max}}$ (kHz)	24 000	2169	821	734	344	260	187	93
$\mu$	1.2	0.21	0.08	0.07	0.03	0.03	0.02	0.01
$dN_{\text{ch}}/d\eta$ (MB)	7	70	151	152	275	400	434	682
at $R = 0.5$ cm								
$R_{\text{hit}}$ (MHz/cm <sup>2</sup> )	94	85	69	62	53	58	46	35
NIEL (1 MeV $n_{\text{eq}}$ /cm <sup>2</sup> )	$1.8 \times 10^{14}$	$1.0 \times 10^{14}$	$8.6 \times 10^{13}$	$7.9 \times 10^{13}$	$6.0 \times 10^{13}$	$3.3 \times 10^{13}$	$4.1 \times 10^{13}$	$1.9 \times 10^{13}$
TID (Rad)	$5.8 \times 10^6$	$3.2 \times 10^6$	$2.8 \times 10^6$	$2.5 \times 10^6$	$1.9 \times 10^6$	$1.1 \times 10^6$	$1.3 \times 10^6$	$6.1 \times 10^5$
at $R = 100$ cm								
$R_{\text{hit}}$ (kHz/cm <sup>2</sup> )	2.4	2.1	1.7	1.6	1.3	1.0	1.1	0.9
NIEL (1 MeV $n_{\text{eq}}$ /cm <sup>2</sup> )	$4.9 \times 10^9$	$2.5 \times 10^9$	$2.1 \times 10^9$	$2.0 \times 10^9$	$1.5 \times 10^9$	$8.3 \times 10^8$	$1.0 \times 10^9$	$4.7 \times 10^8$
TID (Rad)	$1.4 \times 10^2$	$8.0 \times 10^1$	$6.9 \times 10^1$	$6.3 \times 10^1$	$4.8 \times 10^1$	$2.7 \times 10^1$	$3.3 \times 10^1$	$1.5 \times 10^1$